LAN7500/LAN7500i

Hi-Speed USB 2.0 to 10/100/1000 Ethernet Controller

Highlights

- Single Chip Hi-Speed USB 2.0 to 10/100/1000 Ethernet Controller
- 10/100/1000 Ethernet MAC with Full-Duplex Support
- 10/100/1000 Ethernet PHY with HP Auto-MDIX
- Integrated USB 2.0 Hi-Speed Device Controller
- Integrated USB 2.0 Hi-Speed PHY
- Implements Reduced Power Operating Modes
- Supports EEPROM-less Operation for Reduced BOM
- NetDetach provides automatic USB attach/detach when Ethernet cable is connected/removed

Target Applications

- Embedded Systems/CE Devices
- Set-Top Boxes/PVRs
- Networked Printers
- USB Port Replicators
- Standalone USB to Ethernet Dongles
- Test Instrumentation/Industrial

Key Benefits

- USB Device Controller
  - Fully compliant with USB Specification Revision 2.0
  - Supports HS (480 Mbps) and FS (12 Mbps) modes
  - Four endpoints supported
  - Supports vendor specific commands
  - Integrated USB 2.0 PHY
  - Remote wakeup supported
  - High-Performance 10/100/1000 Ethernet Controller
  - Fully compliant with IEEE802.3/802.3u/802.3ab
  - Integrated Ethernet MAC and PHY
  - 10BASE-T, 100BASE-TX, and 1000BASE-T support
  - Full- and half-duplex capability (only full-duplex operation at 1000Mbps)
  - Full-duplex flow control
  - Preamble generation and removal
  - Automatic 32-bit CRC generation and checking
  - 9 KB jumbo frame support
  - Automatic payload padding and pad removal
  - Loop-back modes
  - Supports checksum offloads (IPv4, IPv6, TCP, UDP)
  - Supports Microsoft NDIS 6.2 large send offload
  - Supports IEEE 802.1q VLAN tagging
    - Ability to add and strip IEEE 802.1q VLAN tags
    - VLAN tag based packet filtering (all 4096 VIDs)
  - Flexible address filtering modes
    - 33 exact matches (unicast or multicast)
    - 512-bit hash filter for multicast frames
    - Pass all multicast
    - Promiscuous unicast/multicast modes
    - Inverse filtering
    - Pass all incoming with status report
  - Wakeup packet support
    - Perfect DA frame, wakeup frame, magic packet, broadcast frame, IPv6 & IPv4 TCP SYN
    - 8 programmable 128-bit wakeup frame filters
  - ARP and NS offload
  - PME pin support
  - Integrated Ethernet PHY
    - Auto-negotiation
    - Automatic polarity detection and correction
    - HP Auto-MDIX support
    - Link status change wake-up detection
  - Support for 5 status LEDs
  - Supports various statistical counters
- Power and I/Os
  - Various low power modes
  - 12 GPIOs
  - Supports bus-powered and self-powered operation
  - Variable voltage I/O supply (2.5V/3.3V)
- Miscellaneous Features
  - EEPROM Controller
  - IEEE 1149.1 (JTAG) Boundary Scan
  - Requires single 25 MHz crystal
- Software
  - Windows XP/ Vista / Windows 7 Driver
  - Linux Driver
  - Win CE Driver
  - MAC OS Driver
  - EEPROM/Manufacturing Utility for Windows/DOS
  - PXE Support
  - DOS ODI Driver
- Packaging
  - 56-pin QFN (8x8 mm), RoHS compliant
- Environmental
  - Commercial Temperature Range (0°C to +70°C)
  - Industrial Temperature Range (-40°C to +85°C)

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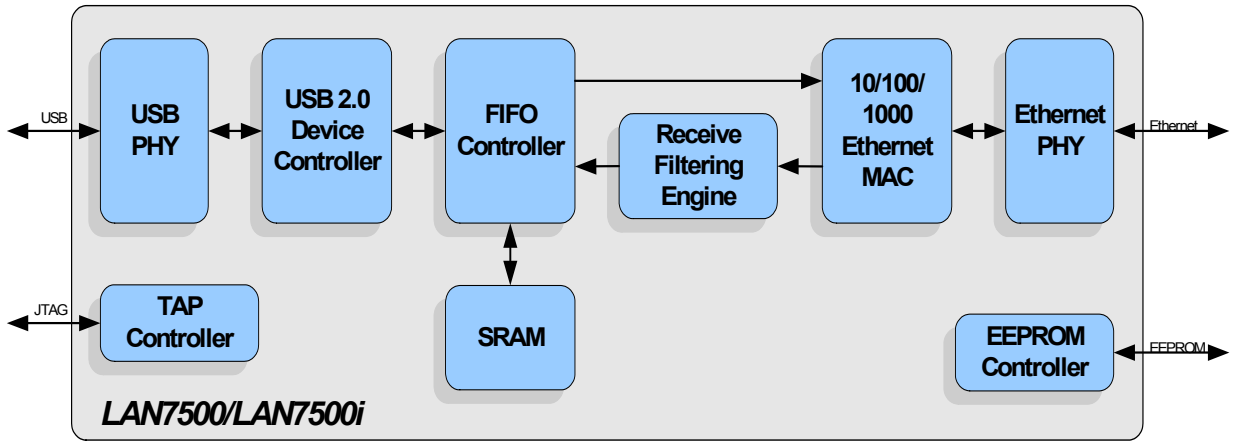
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1.0 INTRODUCTION

1.1 Block Diagram

FIGURE 1-1: LAN7500/LAN7500I SYSTEM DIAGRAM



1.1.1 OVERVIEW

The LAN7500/LAN7500i is a high performance Hi-Speed USB 2.0 to 10/100/1000 Ethernet controller. With applications ranging from embedded systems, set-top boxes, and PVRs, to USB port replicators, USB to Ethernet dongles, and test instrumentation, the device is a high performance and cost competitive USB to Ethernet connectivity solution.

The LAN7500/LAN7500i contains an integrated 10/100/1000 Ethernet MAC and PHY, Filtering Engine, USB PHY, Hi-Speed USB 2.0 device controller, TAP controller, EEPROM controller, and a FIFO controller with a total of 32 KB of internal packet buffering.

The internal USB 2.0 device controller and USB PHY are compliant with the USB 2.0 Hi-Speed standard. The device implements Control, Interrupt, Bulk-in, and Bulk-out USB Endpoints.

The Ethernet controller supports auto-negotiation, auto-polarity correction, HP Auto-MDIX, and is compliant with the IEEE 802.3, IEEE 802.3u, IEEE 802.3ab standards. ARP and NS offload is also supported.

Multiple power management features are provided, including various low power modes and “Magic Packet”, “Wake On LAN”, and “Link Status Change” wake events. These wake events can be programmed to initiate a USB remote wakeup.

An internal EEPROM controller exists to load various USB configuration information and the device MAC address. The integrated IEEE 1149.1 compliant TAP controller provides boundary scan via JTAG.

1.1.2 USB

The USB portion of the LAN7500/LAN7500i integrates a Hi-Speed USB 2.0 device controller and USB PHY.

The USB device controller contains a USB low-level protocol interpreter which implements the USB bus protocol, packet generation/extraction, PID/Device ID parsing, and CRC coding/decoding, with autonomous error handling. The USB device controller is capable of operating in USB 2.0 Hi-Speed and Full-Speed compliant modes and contains autonomous protocol handling functions such as handling of suspend/resume/reset conditions, remote wakeup, and stall condition clearing on Setup packets. The USB device controller also autonomously handles error conditions such as retry for CRC and data toggle errors, and generates NYET, STALL, ACK and NACK handshake responses, depending on the endpoint buffer status.

The LAN7500/LAN7500i implements four USB endpoints: Control, Interrupt, Bulk-in, and Bulk-out. The Bulk-in and Bulk-out Endpoints allow for Ethernet reception and transmission respectively. Implementation of vendor-specific commands allows for efficient statistics gathering and access to the device’s system control and status registers.

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1.1.3 FIFO CONTROLLER

The FIFO controller uses two internal SRAMs to buffer RX and TX traffic. Bulk-Out packets from the USB controller are directly stored into the TX buffer. The FIFO Controller is responsible for extracting Ethernet frames from the USB packet data and passing the frames to the MAC. Received Ethernet Frames are filtered by the Receive Filtering Engine and frames meeting the filtering constraints are stored into the RX buffer and become the basis for bulk-in packets.

1.1.4 ETHERNET

The LAN7500/LAN7500i integrates an IEEE 802.3/802.3u/802.3ab compliant PHY for twisted pair Ethernet applications and a 10/100/1000 Ethernet Media Access Controller (MAC).

The PHY can be configured for 1000 Mbps (1000BASE-T), 100 Mbps (100BASE-TX) or 10 Mbps (10BASE-T) operation in Full-Duplex mode. It can be configured for 100 Mbps or 10 Mbps operation in Half Duplex mode. The PHY block includes auto-negotiation, auto-polarity correction, and Auto-MDIX. Minimal external components are required for the utilization of the Integrated PHY.

The Ethernet MAC/PHY supports numerous power management wakeup features, including “Magic Packet”, “Wake on LAN”, and “Link Status Change”. Microsoft NDIS 6.2 and Windows 7 compliant ARP and NS offload support is also provided.The device will respond to an NS or ARP request by generating and transmitting a response. When received in a SUSPEND state, an NS or ARP request will not result in the generation of a wake event. Additionally, five status LEDs are supported.

1.1.5 FRAME FILTERING

The LAN7500/LAN7500i Receive Filtering Engine performs frame filtering. It supports 33 perfect address filters. These can be used to filter either the Ethernet source address or destination address. Additional address filtering is available via a 512-bit hash filter. The hash filter can perform unicast or multicast filtering.

VLAN tagged frames can be filtered via the VLAN ID. A 4096-bit table exists to support all possible VLAN IDs. The VLAN type can be programmed. Double tagging is supported.

1.1.6 HOST OFFLOADING

The LAN7500/LAN7500i supports a variety of TCP/UDP/IP checksum offloads to reduce the burden on the host processor. For Ethernet receive frames, the device can be configured to validate the IP checksum and UDP/TCP checksum. Both IPv4 and IPv6 packets are supported. A raw checksum across the layer 3 packet can also be provided.

For Ethernet transmitted frames, the device can be configured to calculate the IP checksum and UDP/TCP checksum. Additionally, Large Send Offload (LSO) is supported to further reduce host CPU loading.

1.1.7 POWER MANAGEMENT

The LAN7500/LAN7500i features four variations of USB suspend: SUSPEND0, SUSPEND1, SUSPEND2, and SUSPEND3. These modes allow the application to select the ideal balance of remote wakeup functionality and power consumption.

- **SUSPEND0:** Supports GPIO, “Wake On LAN”, “Magic Packet”, and “PHY Link Up” remote wakeup events. It, however, consumes the most power.
- **SUSPEND1:** Supports GPIO and “Link Status Change” for remote wakeup events. This suspend state consumes less power than SUSPEND0.
- **SUSPEND2:** Supports only GPIO assertion for a remote wakeup event. This is the default suspend mode for the device.
- **SUSPEND3:** Supports GPIO, “Good Packet”, and “PHY Link Up” remote wakeup events. A “Good Packet” is a received frame that is free of errors and passes certain filtering constraints independent of those imposed on “Wake On LAN” and “Magic Packet” frames. This suspend state consumes power at a level similar to the NORMAL state, however, it allows for power savings in the Host CPU, which greatly exceeds that of the LAN7500/LAN7500i. The driver may place the device in this state after prolonged periods of not receiving any Ethernet traffic.

1.1.8 EEPROM CONTROLLER

The LAN7500/LAN7500i contains an EEPROM controller for connection to an external EEPROM. This allows for the automatic loading of static configuration data upon pin reset, or software reset. The EEPROM can be configured to load USB descriptors, USB device configuration, and MAC address.

Custom operation without EEPROM is also provided.

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1.1.9 GENERAL PURPOSE I/O

Twelve GPIOs are supported. All GPIOs can serve as remote wakeup events when the LAN7500/LAN7500i is in a suspended state.

1.1.10 TAP CONTROLLER

IEEE 1149.1 compliant TAP Controller supports boundary scan and various test modes.

The device includes an integrated JTAG boundary-scan test port for board-level testing. The interface consists of four pins (TDO, TDI, TCK and TMS) and includes a state machine, data register array, and an instruction register. The JTAG pins are described in Table 2-3, “JTAG Pins,” on page 10. The JTAG interface conforms to the IEEE Standard 1149.1 - *1990 Standard Test Access Port (TAP) and Boundary-Scan Architecture*.

All input and output data is synchronous to the TCK test clock input. TAP input signals TMS and TDI are clocked into the test logic on the rising edge of TCK, while the output signal TDO is clocked on the falling edge.

The JTAG logic is reset when the TMS and TDI pins are high for five TCK periods.

The implemented IEEE 1149.1 instructions and their op codes are shown in Table 1-1.

TABLE 1-1: EEE 1149.1 OP CODES

Instruction	Op Code	Comment
Bypass	111	Mandatory Instruction
Sample/Preload	010	Mandatory Instruction
EXTEST	000	Mandatory Instruction
Clamp	011	Optional Instruction
HIGHZ	100	Optional Instruction
IDCODE	001	Optional Instruction

Note: All digital I/O pins support IEEE 1149.1 operation. Analog pins and the XO pin do not support IEEE 1149.1 operation.

1.1.11 TEST FEATURES

Read/Write access to internal SRAMs is provided via the devices registers. JTAG based USB BIST is available.

1.1.12 SYSTEM SOFTWARE

LAN7500/LAN7500i software drivers are available for the following operating systems:

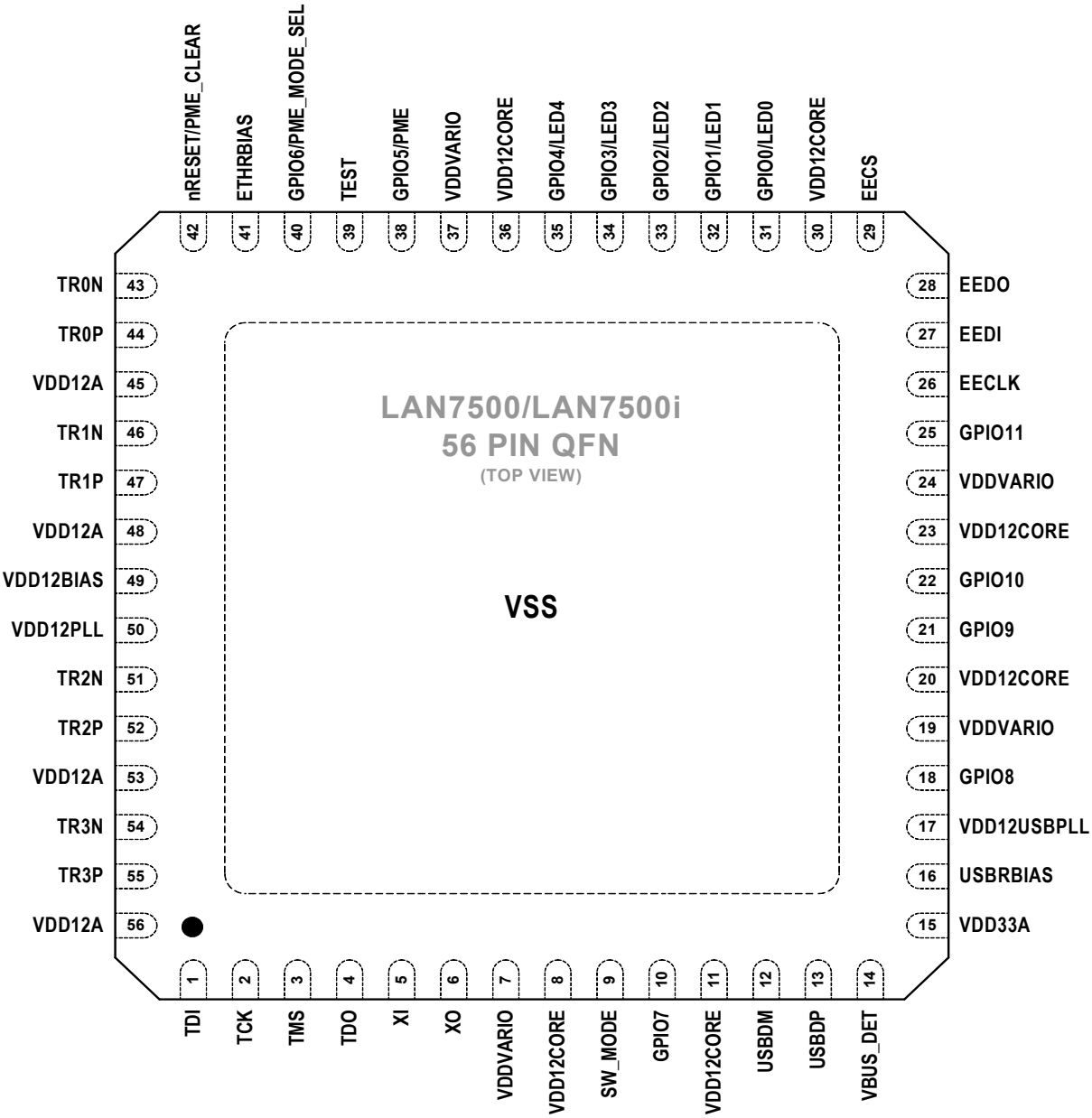
- Windows XP/ Vista/ Windows 7
- Win CE
- Linux
- MAC OS
- DOS ODI

In addition, an EEPROM programming utility is available for configuring the external EEPROM. PXE Support is also available.

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2.0 PIN DESCRIPTION AND CONFIGURATION

FIGURE 2-1: LAN7500/LAN7500I 56-QFN PIN ASSIGNMENTS (TOP VIEW)



NOTE: Exposed pad (VSS) on bottom of package must be connected to ground

TABLE 2-1: GPIO PINS

Num PINs	Name	Symbol	Buffer Type	Description
1	Indicator LED0	LED0	VOD8	Used in conjunction with LED1. May be programmed to indicate Link and Speed or Link and Speed and Activity.
	General Purpose I/O 0	GPIO0	VIS/VO8/ VOD8 (PU)	This General Purpose I/O pin is fully programmable as either a push-pull output, an open-drain output, or a Schmitt-triggered input. **Note:** This pin is configured as a GPIO by default.
1	Indicator LED1	LED1	VOD8	Used in conjunction with LED0. May be programmed to indicate Ethernet Link and Speed or Link and Speed and Activity.
	General Purpose I/O 1	GPIO1	VIS/VO8/ VOD8 (PU)	This General Purpose I/O pin is fully programmable as either a push-pull output, an open-drain output, or a Schmitt-triggered input. **Note:** This pin is configured as a GPIO by default.
1	Indicator LED2	LED2	VOD8	May be programmed to indicate Ethernet Link and Activity or just Activity.
	General Purpose I/O 2	GPIO2	VIS/VO8/ VOD8 (PU)	This General Purpose I/O pin is fully programmable as either a push-pull output, an open-drain output, or a Schmitt-triggered input. **Note:** This pin is configured as a GPIO by default.
1	Indicator LED3	LED3	VOD8	May be programmed for use as an Ethernet Link indicator.
	General Purpose I/O 3	GPIO3	VIS/VO8/ VOD8 (PU)	This General Purpose I/O pin is fully programmable as either a push-pull output, an open-drain output, or a Schmitt-triggered input. **Note:** This pin is configured as a GPIO by default.
1	Indicator LED4	LED4	VOD8	May be programmed to indicate Ethernet Full Duplex operation.
	General Purpose I/O 4	GPIO4	VIS/VO8/ VOD8 (PU)	This General Purpose I/O pin is fully programmable as either a push-pull output, an open-drain output, or a Schmitt-triggered input.
1	PME	PME	VO8/ VOD8	This pin may be used to signal PME when PME mode of operation is in effect. Refer to Section 4.0, "PME Operation," on page 27 for additional information.
	General Purpose I/O 5	GPIO5	VIS/VO8/ VOD8 (PU)	This General Purpose I/O pin is fully programmable as either a push-pull output, an open-drain output, or a Schmitt-triggered input.

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TABLE 2-1: GPIO PINS (CONTINUED)

Num PINs	Name	Symbol	Buffer Type	Description
1	PME Mode Select	PME_MODE_-SEL	VIS (PU)	This pin may serve as the PME_MODE_SEL input when PME mode of operation is in effect. Refer to Section 4.0, "PME Operation," on page 27 for additional information.
	General Purpose I/O 6	GPIO6	VIS/VO8/ VOD8 (PU)	This General Purpose I/O pin is fully programmable as either a push-pull output, an open-drain output, or a Schmitt-triggered input.
1	General Purpose I/O 7	GPIO7	VIS/VO8/ VOD8 (PU)	This General Purpose I/O pin is fully programmable as either a push-pull output, an open-drain output, or a Schmitt-triggered input.
1	General Purpose I/O 8	GPIO8	VIS/VO6/ VOD6 (PU)	This General Purpose I/O pin is fully programmable as either a push-pull output, an open-drain output, or a Schmitt-triggered input.
1	General Purpose I/O 9	GPIO9	VIS/VO8/ VOD8 (PU)	This General Purpose I/O pin is fully programmable as either a push-pull output, an open-drain output, or a Schmitt-triggered input.
1	General Purpose I/O 10	GPIO10	VIS/VO8/ VOD8 (PU)	This General Purpose I/O pin is fully programmable as either a push-pull output, an open-drain output, or a Schmitt-triggered input.
1	General Purpose I/O 11	GPIO11	VIS/VO8/ VOD8 (PU)	This General Purpose I/O pin is fully programmable as either a push-pull output, an open-drain output, or a Schmitt-triggered input.

TABLE 2-2: EEPROM PINS

Num PINs	Name	Symbol	Buffer Type	Description
1	EEPROM Data In	EEDI	VIS (PD)	This pin is driven by the EEDO output of the external EEPROM.
1	EEPROM Data Out	EEDO	VO8	This pin drives the EEDI input of the external EEPROM.
1	EEPROM Chip Select	EECS	VO8	This pin drives the chip select output of the external EEPROM. **Note:** The EECS output may tri-state briefly during power-up. Some EEPROM devices may be prone to false selection during this time. When an EEPROM is used, an external pull-down resistor is recommended on this signal to prevent false selection. Refer to your EEPROM manufacturer's datasheet for additional information.
1	EEPROM Clock	EECLK	VO8	This pin drives the EEPROM clock of the external EEPROM.

TABLE 2-3: JTAG PINS

Num PINs	Name	Symbol	Buffer Type	Description
1	JTAG Test Data Out	TDO	VO8	JTAG (IEEE 1149.1) data output.
1	JTAG Test Data Input	TDI	VIS (PU)	JTAG (IEEE 1149.1) data input. **Note:** When not used, tie this pin to VDDVARIO.
1	JTAG Test Clock	TCK	VIS (PD)	JTAG (IEEE 1149.1) test clock. **Note:** When not used, tie this pin to VSS.
1	JTAG Test Mode Select	TMS	VIS (PU)	JTAG (IEEE 1149.1) test mode select. **Note:** When not used, tie this pin to VDDVARIO.

TABLE 2-4: USB PINS

Num PINs	Name	Symbol	Buffer Type	Description
1	USB DMINUS	USBDM	AIO	**Note:** The functionality of this pin may be swapped to USB DPLUS via the Port Swap bit of Configuration Flags 0.
1	USB DPLUS	USBDP	AIO	**Note:** The functionality of this pin may be swapped to USB DMINUS via the Port Swap bit of Configuration Flags 0.
1	External USB Bias Resistor.	USBRBIAS	AI	Used for setting HS transmit current level and on-chip termination impedance. Connect to an external 12K 1.0% resistor to ground.

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TABLE 2-5: ETHERNET PHY PINS

Num PINs	Name	Symbol	Buffer Type	Description
1	Crystal Input	XI	ICLK	External 25 MHz crystal input. **Note:** This pin can also be driven by a single-ended clock oscillator. When this method is used, XO should be left unconnected
1	Crystal Output	XO	OCLK	External 25 MHz crystal output.
1	Ethernet TX/RX Positive Channel 0	TR0P	AIO	Transmit/Receive Positive Channel 0.
1	Ethernet TX/RX Negative Channel 0	TR0N	AIO	Transmit/Receive Negative Channel 0.
1	Ethernet TX/RX Positive Channel 1	TR1P	AIO	Transmit/Receive Positive Channel 1.
1	Ethernet TX/RX Negative Channel 1	TR1N	AIO	Transmit/Receive Negative Channel 1.
1	Ethernet TX/RX Positive Channel 2	TR2P	AIO	Transmit/Receive Positive Channel 2.
1	Ethernet TX/RX Negative Channel 2	TR2N	AIO	Transmit/Receive Negative Channel 2.
1	Ethernet TX/RX Positive Channel 3	TR3P	AIO	Transmit/Receive Positive Channel 3.
1	Ethernet TX/RX Negative Channel 3	TR3N	AIO	Transmit/Receive Negative Channel 3.
1	External PHY Bias Resistor	ETHRBIAS	AI	Used for the internal bias circuits. Connect to an external 8.06K 1.0% resistor to ground.

TABLE 2-6: MISCELLANEOUS PINS

Num PINs	Name	Symbol	Buffer Type	Description
1	System Reset	nRESET	VIS (PU)	This active-low pin allows external hardware to reset the device. **Note:** Assertion of nRESET is required following power-on.
	PME Clear	PME_CLEAR	VIS (PU)	This pin may serve as the PME_CLEAR input when PME mode of operation is in effect. Refer to Section 4.0, "PME Operation," on page 27 for additional information.
1	Detect Upstream VBUS Power	VBUS_DET	IS_5V (PD)	Detects state of upstream bus power. For bus powered operation, this pin must be tied to VDD33A. For self powered operation, refer to the LAN7500/LAN7500i reference schematics.
1	Test	TEST	-	This pin must always be connected to VSS for proper operation.
1	Switching Regulator Mode	SW_MODE	VO6	When asserted, this pin places the external switching regulator into power saving mode. **Note:** The SW_MODE_POL and SW_MODE_SEL bits of Configuration Flags 1 control the polarity of the pin and when it is asserted, respectively.

TABLE 2-7: I/O POWER PINS, CORE POWER PINS, AND GROUND PAD

Num PINs	Name	Symbol	Buffer Type	Description
1	+3.3V Analog Power Supply Input	VDD33A	P	Refer to Section 6.0, "Application Diagrams," on page 32 and the LAN7500/LAN7500i reference schematics for connection information.
4	+3.3V/+2.5V I/O Power Supply Input	VDDVARIO	P	Refer to Section 6.0, "Application Diagrams," on page 32 and the LAN7500/LAN7500i reference schematics for connection information.
6	Digital Core +1.2V Power Supply Input	VDD12CORE	P	Refer to Section 6.0, "Application Diagrams" and the LAN7500/LAN7500i reference schematics for connection information.
1	USB PLL +1.2V Power Supply Input	VDD12USBPLL	P	Refer to Section 6.0, "Application Diagrams," on page 32 and the LAN7500/LAN7500i reference schematics for additional connection information.
4	Ethernet +1.2V Port Power Supply Input For Channels 0-3	VDD12A	P	Refer to Section 6.0, "Application Diagrams," on page 32 and the LAN7500/LAN7500i reference schematics for additional connection information.

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TABLE 2-7: I/O POWER PINS, CORE POWER PINS, AND GROUND PAD (CONTINUED)

Num PINs	Name	Symbol	Buffer Type	Description
1	Ethernet +1.2V Bias Power Supply Input	VDD12BIAS	P	Refer to Section 6.0, "Application Diagrams," on page 32 and the LAN7500/LAN7500i reference schematics for additional connection information.
1	Ethernet PLL +1.2V Power Supply Input	VDD12PLL	P	Refer toSection 6.0, "Application Diagrams," on page 32 and the LAN7500/LAN7500i reference schematics for additional connection information.
Exposed pad on package bottom (FIGURE 2-1:)	Ground	VSS	P	Common Ground

2.1 Pin Assignments

TABLE 2-8: 56-QFN PACKAGE PIN ASSIGNMENTS

Pin Num	Pin Name	Pin Num	Pin Name	Pin Num	Pin Name	Pin Num	Pin Name
1	TDI	15	VDD33A	29	EECS	43	TR0N
2	TCK	16	USBRBIAS	30	VDD12CORE	44	TR0P
3	TMS	17	VDD12USBPLL	31	GPIO0/LED0	45	VDD12A
4	TDO	18	GPIO8	32	GPIO1/LED1	46	TR1N
5	XI	19	VDDVARIO	33	GPIO2/LED2	47	TR1P
6	XO	20	VDD12CORE	34	GPIO3/LED3	48	VDD12A
7	VDDVARIO	21	GPIO9	35	GPIO4/LED4	49	VDD12BIAS
8	VDD12CORE	22	GPIO10	36	VDD12CORE	50	VDD12PLL
9	SW_MODE	23	VDD12CORE	37	VDDVARIO	51	TR2N
10	GPIO7	24	VDDVARIO	38	GPIO5/PME	52	TR2P
11	VDD12CORE	25	GPIO11	39	TEST	53	VDD12A
12	USBDM	26	EECLK	40	GPIO6/ PME_MODE_-SEL	54	TR3N
13	USBDP	27	EEDI	41	ETHRBIAS	55	TR3P
14	VBUS_DET	28	EEDO	42	nRESET/ PME_CLEAR	56	VDD12A
EXPOSED PAD MUST BE CONNECTED TO VSS							

2.2 Buffer Types

TABLE 2-9: BUFFER TYPES

Buffer Type	Description
VIS	Variable voltage Schmitt-triggered Input
IS_5V	5V Tolerant Schmitt-triggered Input
VO6	Variable voltage output with 6mA sink and 6mA source
VOD6	Variable voltage open-drain output with 6mA sink
VO8	Variable voltage output with 8mA sink and 8mA source
VOD8	Variable voltage open-drain output with 8mA sink
PU	50uA (typical) internal pull-up. Unless otherwise noted in the pin description, internal pull-ups are always enabled. **Note:** Internal pull-up resistors prevent unconnected inputs from floating. Do not rely on internal resistors to drive signals external to LAN7500/LAN7500i. When connected to a load that must be pulled high, an external resistor must be added.
PD	50uA (typical) internal pull-down. Unless otherwise noted in the pin description, internal pull-downs are always enabled. **Note:** Internal pull-down resistors prevent unconnected inputs from floating. Do not rely on internal resistors to drive signals external to LAN7500/LAN7500i. When connected to a load that must be pulled low, an external resistor must be added.
AI	Analog input
AIO	Analog bi-directional
ICLK	Crystal oscillator input pin
OCLK	Crystal oscillator output pin
P	Power pin

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3.0 EEPROM CONTROLLER (EPC)

LAN7500/LAN7500i may use an external EEPROM to store the default values for the USB descriptors and the MAC address. The EEPROM controller supports most “93C56 or 93C66” type 256/512 byte EEPROMs. A total of nine address bits are used for connection to the device.

A 3-wire style 2K/4K EEPROM that is organized for 256/512 x 8-bit operation must be used.

The MAC address is used as the default Ethernet MAC address and is loaded into the device’s MAC address registers. If a properly configured EEPROM is not detected, it is the responsibility of the Host LAN Driver to set the IEEE addresses.

After a system-level reset occurs, the device will load the default values from a properly configured EEPROM. The device will not accept USB transactions from the Host until this process is completed.

The device’s EEPROM controller also allows the Host system to read, write and erase the contents of the Serial EEPROM.

3.1 EEPROM Format

Table 3-1 illustrates the format in which data is stored inside of the EEPROM.

Note the EEPROM offsets are given in units of 16-bit word offsets. A length field with a value of zero indicates that the field does not exist in the EEPROM. The device will use the field’s HW default value in this case.

Note: For the device descriptor, the only valid values for the length are 0 and 18.

Note: For the configuration and interface descriptor, the only valid values for the length are 0 and 18.

Note: The EEPROM programmer must ensure that if a string descriptor does not exist in the EEPROM, the referencing descriptor must contain 00h for the respective string index field.

Note: If all string descriptor lengths are zero, then a Language ID will not be supported.

TABLE 3-1: EEPROM FORMAT

EEPROM Address	EEPROM Contents
00h	A5h (EEPROM Programmed Indicator)
01h	MAC Address [7:0]
02h	MAC Address [15:8]
03h	MAC Address [23:16]
04h	MAC Address [31:24]
05h	MAC Address [39:32]
06h	MAC Address [47:40]
07h	Full-Speed Polling Interval for Interrupt Endpoint
08h	Hi-Speed Polling Interval for Interrupt Endpoint
09h	Configuration Flags 0
0Ah	Language ID Descriptor [7:0]
0Bh	Language ID Descriptor [15:8]
0Ch	Manufacturer ID String Descriptor Length (bytes)
0Dh	Manufacturer ID String Descriptor EEPROM Word Offset
0Eh	Product Name String Descriptor Length (bytes)

TABLE 3-1: EEPROM FORMAT (CONTINUED)

EEPROM Address	EEPROM Contents
0Fh	Product Name String Descriptor EEPROM Word Offset
10h	Serial Number String Descriptor Length (bytes)
11h	Serial Number String Descriptor EEPROM Word Offset
12h	Configuration String Descriptor Length (bytes)
13h	Configuration String Descriptor Word Offset
14h	Interface String Descriptor Length (bytes)
15h	Interface String Descriptor Word Offset
16h	Hi-Speed Device Descriptor Length (bytes)
17h	Hi-Speed Device Descriptor Word Offset
18h	Hi-Speed Configuration and Interface Descriptor Length (bytes)
19h	Hi-Speed Configuration and Interface Descriptor Word Offset
1Ah	Full-Speed Device Descriptor Length (bytes)
1Bh	Full-Speed Device Descriptor Word Offset
1Ch	Full-Speed Configuration and Interface Descriptor Length (bytes)
1Dh	Full-Speed Configuration and Interface Descriptor Word Offset
1Eh	GPIO[7:0] Wakeup Enables Bit x = 0 -> GPIOx Pin Disabled for Wakeup Use. Bit x = 1 -> GPIOx Pin Enabled for Wakeup Use.
1Fh	GPI0[11:8] Wakeup Enables Bit x = 0 -> GPIO(x+8) Pin Disabled for Wakeup Use. Bit x = 1 -> GPIO(x+8) Pin Enabled for Wakeup Use. **Note:** Bits 7:4 Unused.
20h	GPIO PME Flags
21h	Configuration Flags 1

Note: EEPROM byte addresses past 21h can be used to store data for any purpose assuming these addresses are not used for descriptor storage.

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Table 3-2 describes the Configuration Flags 0 byte. If a configuration descriptor exists in the EEPROM, it will override the values in Configuration Flags 0.

TABLE 3-2: CONFIGURATION FLAGS 0

Bits	Description
7	**Port Swap** This bit facilitates swapping the mapping of USBDP and USBDM. 0 = USBDP maps to the USB D+ line and USBDM maps to the USB D- line. 1 = USBDP maps to the USB D- line. USBDM maps to the USB D+ line.
6:5	**PHY Boost** This field provides the ability to boost the electrical drive strength of the HS output current to the upstream port. 00 = Normal electrical drive strength. 01 = Elevated electrical drive strength (+4% boost). 10 = Elevated electrical drive strength (+8% boost). 11 = Elevated electrical drive strength (+12% boost).
4	**Duplex Detection** This bit determines whether duplex operational mode is detected automatically or manually set. 0 = Manual 1 = Automatic
3	**Speed Detection** This bit determines whether operational speed is detected automatically or manually set. 0 = Manual 1 = Automatic

TABLE 3-2: CONFIGURATION FLAGS 0 (CONTINUED)

<table>
<tr><th>Bits</th><th>Description</th></tr>
<tr><td>2</td><td>SPD_LED_FUNCTION
This bit specifies the functionality of speed LEDs (LED0 and LED1). The Speed LEDs' behavior is determined by line speed and the setting of this bit, as indicated in following table:

<table>
<tr><th>SPD_LED_FUNCTION</th><th>SPEED (Mbps)</th><th>LED0</th><th>LED1</th></tr>
<tr><td>0</td><td>No Link</td><td>Off</td><td>Off</td></tr>
<tr><td>0</td><td>10</td><td>On</td><td>Off</td></tr>
<tr><td>0</td><td>100</td><td>Off</td><td>On</td></tr>
<tr><td>0</td><td>1000</td><td>On</td><td>On</td></tr>
<tr><td>1</td><td>No Link</td><td>Off</td><td>Off</td></tr>
<tr><td>1</td><td>10</td><td>Blink</td><td>Off</td></tr>
<tr><td>1</td><td>100</td><td>Off</td><td>Blink</td></tr>
<tr><td>1</td><td>1000</td><td>Blink</td><td>Blink</td></tr>
</table>
When SPD_LED_FUNCTION = 0, the LEDs function solely as Link and Speed LEDs. When SPD_LED_FUNCTION = 1, the LEDs function as Link and Speed and Activity LEDs. In those cases, the table entry “Blink” indicates the LED will remain on when no transmit or receive activity is detected and will blink at an 80 mS rate whenever TX or RX activity is detected.

Note: GPIOEN[1:0] in Configuration Flags 1 must be set in order to properly control speed LED operation. If only one of the bits is set, then untoward operation and unexpected results may occur. If both bits are clear, then SPD_LED_FUNCTION is ignored.</td></tr>
<tr><td>1</td><td>Remote Wakeup Support

0 = Device does not support remote wakeup.
1 = Device supports remote wakeup.</td></tr>
<tr><td>0</td><td>Power Method

0 = Device is bus powered.
1 = Device is self powered.</td></tr>
</table>

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Table 3-3 describes the Configuration Flags 1.

TABLE 3-3: CONFIGURATION FLAGS 1

Bits	Description
7	**LED2_FUNCTION** This bit specifies the functionality of LED2. 0 = Link and Activity LED. 1 = Activity LED. **Note:** This bit is ignored if GPIOEN2 is not set in this flag byte.
6:2	**GPIOEN[4:0]** This field specifies GPIO/LED functionality for GPIO[4:0]. 0 = GPIOn Pin Functions as GPIO pin. 1 = GPIOn Pin Functions as LED.
1	**SW_MODE_SEL** This bit specifies the modes of operation during which the SW_MODE pin will be asserted. 0 = SW_MODE asserted in SUSPEND2. 1 = SW_MODE asserted in SUSPEND2, SUSPEND1, and NetDetach.
0	**SW_MODE_POL** This bit selects the polarity of the SW_MODE pin. 0 = Active low. 1 = Active high.

Table 3-4 describes the GPIO PME flags.

TABLE 3-4: GPIO PME FLAGS

Bits	Description
7	**GPIO PME Enable** Setting this bit enables the assertion of the GPIO5 pin, as a result of a Wakeup (GPIO) pin, Magic Packet, or PHY Link Up. The host processor may use the GPIO5 pin to asynchronously wake up, in a manner analogous to a PCI PME pin. 0 = The device does not support GPIO PME signaling. 1 = The device supports GPIO PME signaling. **Note:** When this bit is 0, the remaining GPIO PME parameters in this flag byte are ignored.
6	**GPIO PME Configuration** This bit selects whether the GPIO PME is signaled on the GPIO5 pin as a level or a pulse. If pulse is selected, the duration of the pulse is determined by the setting of the GPIO PME Length bit of this flag byte. The level of the signal or the polarity of the pulse is determined by the GPIO PME Polarity bit of this flag byte. 0 = GPIO PME is signaled via a level. 1 = GPIO PME is signaled via a pulse. **Note:** If GPIO PME Enable is 0, this bit is ignored.

TABLE 3-4: GPIO PME FLAGS (CONTINUED)

Bits	Description
5	**GPIO PME Length** When the GPIO PME Configuration bit of this flag byte indicates that the GPIO PME is signaled by a pulse on the GPIO5 pin, this bit determines the duration of the pulse. 0 = GPIO PME pulse length is 1.5 mS. 1 = GPIO PME pulse length is 150 mS. **Note:** If GPIO PME Enable is 0, this bit is ignored.
4	**GPIO PME Polarity** Specifies the level of the signal or the polarity of the pulse used for GPIO PME signaling. 0 = GPIO PME signaling polarity is low. 1 = GPIO PME signaling polarity is high. **Note:** If GPIO PME Enable is 0, this bit is ignored.
3	**GPIO PME Buffer Type** This bit selects the output buffer type for GPIO5. 0 = Open drain driver / open source 1 = Push-Pull driver **Note:** Buffer Type = 0, Polarity = 0 implies Open Drain Buffer Type = 0, Polarity = 1 implies Open Source **Note:** If GPIO PME Enable is 0, this bit is ignored.
2	**GPIO PME WOL Select** Four types of wakeup events are supported; Magic Packet, Perfect DA, PHY Link Up, and Wakeup Pin(s) assertion. Wakeup Pin(s) are selected via the GPIO Wakeup Enables specified in bytes 1Eh and 1Fh of the EEPROM. This bit selects whether WOL events or Link Up wakeup events are supported. 0 = WOL event wakeup supported. 1 = PHY linkup wakeup supported. **Note:** If WOL is selected, the PME Magic Packet Enable and PME Perfect DA Enable bits determine the WOL event(s) that will cause a wakeup. **Note:** If GPIO PME Enable is 0, this bit is ignored.
1	**PME Magic Packet Enable** When GPIO PME WOL Select indicates WOL is selected, this bit enables/disables Magic Packet detection and wakeup. 0 = Magic Packet event wakeup disabled. 1 = Magic Packet event wakeup enabled. **Note:** This bit is ignored if GPIO PME WOL Select indicates WOL event wakeup not supported.
0	**PME Perfect DA Enable** When GPIO PME WOL Select indicates WOL is selected, this bit enables/disables Perfect DA detection and wakeup. 0 = Perfect DA event wakeup disabled. 1 = Perfect DA event wakeup enabled. **Note:** This bit is ignored if GPIO PME WOL Select indicates WOL event wakeup not supported.

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3.2 EEPROM Defaults

The signature value of 0xA5 is stored at address 0. A different signature value indicates to the EEPROM controller that no EEPROM or an un-programmed EEPROM is attached to the device. In this case, the hardware default values are used, as shown in Table 3-5.

TABLE 3-5: EEPROM DEFAULTS

Field	Default Value
MAC Address	FFFFFFFFFFFFh
Full-Speed Polling Interval (mS)	01h
Hi-Speed Polling Interval (mS)	04h
Configuration Flags 0	1Bh
Maximum Power (mA)	FAh
Vendor ID	0424h
Product ID	7500h

Note: Refer to the LAN7500/LAN7500i Vendor/Product ID application note for details on proper usage of these fields.

3.3 EEPROM Auto-Load

Certain system level resets (USB reset, nRESET, and SRST) cause the EEPROM contents to be loaded into the device. After a reset, the EEPROM controller attempts to read the first byte of data from the EEPROM. If the value A5h is read from the first address, then the EEPROM controller will assume that a programmed external Serial EEPROM is present.

Note: The USB reset only loads the MAC address.

3.4 An Example of EEPROM Format Interpretation

Table 3-6 and Table 3-7 provide an example of how the contents of a EEPROM are formatted. Table 3-6 is a dump of the EEPROM memory (256-byte EEPROM), while Table 3-7 illustrates, byte by byte, how the EEPROM is formatted. The industrial version of the device is used in the example.

TABLE 3-6: DUMP OF EEPROM MEMORY

Offset Byte	Value (Hex)
0000h	A5 12 34 56 78 9A BC 01
0008h	04 1E 09 04 0A 0F 12 14
0010h	10 1D 00 00 00 00 12 25
0018h	12 2E 12 37 12 40 00 04
0020h	8A 7C 0A 03 53 00 4D 00
0028h	53 00 43 00 12 03 4C 00
0030h	41 00 4E 00 37 00 35 00
0038h	30 00 30 00 69 00 10 03

TABLE 3-6: DUMP OF EEPROM MEMORY

Offset Byte	Value (Hex)
0040h	30 00 30 00 30 00 35 00
0048h	31 00 32 00 33 00 12 01
0050h	00 02 FF 00 FF 40 24 04
0058h	00 75 00 01 01 02 03 01
0060h	09 02 27 00 01 01 00 A0
0068h	FA 09 04 00 00 03 FF 00
0070h	FF 00 12 01 00 02 FF 00
0078h	FF 40 24 04 00 75 00 01
0080h	01 02 03 01 09 02 27 00
0088h	01 01 00 A0 FA 09 04 00
0090h - 00FFh	00 03 FF 00 FF 00 .....

TABLE 3-7: EEPROM EXAMPLE - 256 BYTE EEPROM

EEPROM Address	EEPROM Contents (Hex)	Description
00h	A5	EEPROM Programmed Indicator
01h - 06h	12 34 56 78 9A BC	MAC Address 12 34 56 78 9A BC
07h	01	Full-Speed Polling Interval for Interrupt Endpoint (1ms)
08h	04	Hi-Speed Polling Interval for Interrupt Endpoint (4ms)
09h	1E	Configuration Flags 0 - No USBDP/USBDM swapping, No PHY Boost, Automatic Duplex and Speed detection, the device is bus powered and supports remote wakeup, LEDs 0 and 1 are used as Link/Speed/Activity LEDs (Since they are enabled as LEDs in Configuration Flags 1 GPI-OEN field).
0Ah - 0Bh	09 04	Language ID Descriptor 0409h, English
0Ch	0A	Manufacturer ID String Descriptor Length (10 bytes)
0Dh	0F	Manufacturer ID String Descriptor EEPROM Word Offset (11h) Corresponds to EEPROM Byte Offset 22h
0Eh	12	Product Name String Descriptor Length (18 bytes)
0Fh	14	Product Name String Descriptor EEPROM Word Offset (16h) Corresponds to EEPROM Byte Offset 2Ch
10h	10	Serial Number String Descriptor Length (16 bytes)
11h	1D	Serial Number String Descriptor EEPROM Word Offset (1Fh) Corresponds to EEPROM Byte Offset 3Eh

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TABLE 3-7: EEPROM EXAMPLE - 256 BYTE EEPROM (CONTINUED)

EEPROM Address	EEPROM Contents (Hex)	Description
12h	00	Configuration String Descriptor Length (0 bytes - NA)
13h	00	Configuration String Descriptor Word Offset (Don't Care)
14h	00	Interface String Descriptor Length (0 bytes - NA)
15h	00	Interface String Descriptor Word Offset (Don't Care)
16h	12	Hi-Speed Device Descriptor Length (18 bytes)
17h	25	Hi-Speed Device Descriptor Word Offset (27h) Corresponds to EEPROM Byte Offset 4Eh
18h	12	Hi-Speed Configuration and Interface Descriptor Length (18 bytes)
19h	2E	Hi-Speed Configuration and Interface Descriptor Word Offset (30h) Corresponds to EEPROM Byte Offset 60h
1Ah	12	Full-Speed Device Descriptor Length (18 bytes)
1Bh	37	Full-Speed Device Descriptor Word Offset (39h) Corresponds to EEPROM Byte Offset 72h
1Ch	12	Full-Speed Configuration and Interface Descriptor Length (18 bytes)
1Dh	40	Full-Speed Configuration and Interface Descriptor Word Offset (42h) Corresponds to EEPROM Byte Offset 84h
1Eh	00	GPIO[7:0] Wake Enables - GPIO[7:0] Not Used For Wakeup Signaling
1Fh	04	GPIO[11:8] Wake Enables - GPIO10 Used For Wakeup Signaling
20h	8A	GPIO PME Flags - PME Signaling Enabled via Low Level, Push-Pull Driver, Magic Packet WOL selected.
21h	7C	Configuration Flags 1 - LED2 is Link and Activity LED, GPIO pins 0 to 4 function as LEDs, SW_MODE pin active low in SUSPEND2 state.
22h	0A	Size of Manufacturer ID String Descriptor (10 bytes)
23h	03	Descriptor Type (String Descriptor - 03h)
24h - 2Bh	53 00 4D 00 53 00 43 00	Manufacturer ID String ("MCHP" in UNICODE)
2Ch	12	Size of Product Name String Descriptor (18 bytes)
2Dh	03	Descriptor Type (String Descriptor - 03h)
2Eh - 3Dh	4C 00 41 00 4E 00 37 00 35 00 30 00 30 00 69 00	Product Name String ("LAN7500i" in UNICODE)
3Eh	10	Size of Serial Number String Descriptor (16 bytes)
3Fh	03	Descriptor Type (String Descriptor - 03h)
40h - 4Dh	30 00 30 00 30 00 35 00 31 00 32 00 33 00	Serial Number String ("0005123" in UNICODE)
4Eh	12	Size of Hi-Speed Device Descriptor in Bytes (18 bytes)

TABLE 3-7: EEPROM EXAMPLE - 256 BYTE EEPROM (CONTINUED)

EEPROM Address	EEPROM Contents (Hex)	Description
4Fh	01	Descriptor Type (Device Descriptor - 01h)
50h - 51h	00 02	USB Specification Number that the device complies with (0200h)
52h	FF	Class Code
53h	00	Subclass Code
54h	FF	Protocol Code
55h	40	Maximum Packet Size for Endpoint 0
56h - 57h	24 04	Vendor ID (0424h)
58h - 59h	00 75	Product ID (7500h)
5Ah - 5Bh	00 01	Device Release Number (0100h)
5Ch	01	Index of Manufacturer String Descriptor
5Dh	02	Index of Product String Descriptor
5Eh	03	Index of Serial Number String Descriptor
5Fh	01	Number of Possible Configurations
60h	09	Size of Hi-Speed Configuration Descriptor in bytes (9 bytes)
61h	02	Descriptor Type (Configuration Descriptor - 02h)
62h - 63h	27 00	Total length in bytes of data returned (0027h = 39 bytes)
64h	01	Number of Interfaces
65h	01	Value to use as an argument to select this configuration
66h	00	Index of String Descriptor describing this configuration
67h	A0	Bus powered and remote wakeup enabled
68h	FA	Maximum Power Consumption is 500 mA
69h	09	Size of Descriptor in Bytes (9 Bytes)
6Ah	04	Descriptor Type (Interface Descriptor - 04h)
6Bh	00	Number identifying this Interface
6Ch	00	Value used to select alternative setting
6Dh	03	Number of Endpoints used for this interface (Less endpoint 0)
6Eh	FF	Class Code
6Fh	00	Subclass Code
70h	FF	Protocol Code
71h	00	Index of String Descriptor Describing this interface
72h	12	Size of Full-Speed Device Descriptor in Bytes (18 Bytes)

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TABLE 3-7: EEPROM EXAMPLE - 256 BYTE EEPROM (CONTINUED)

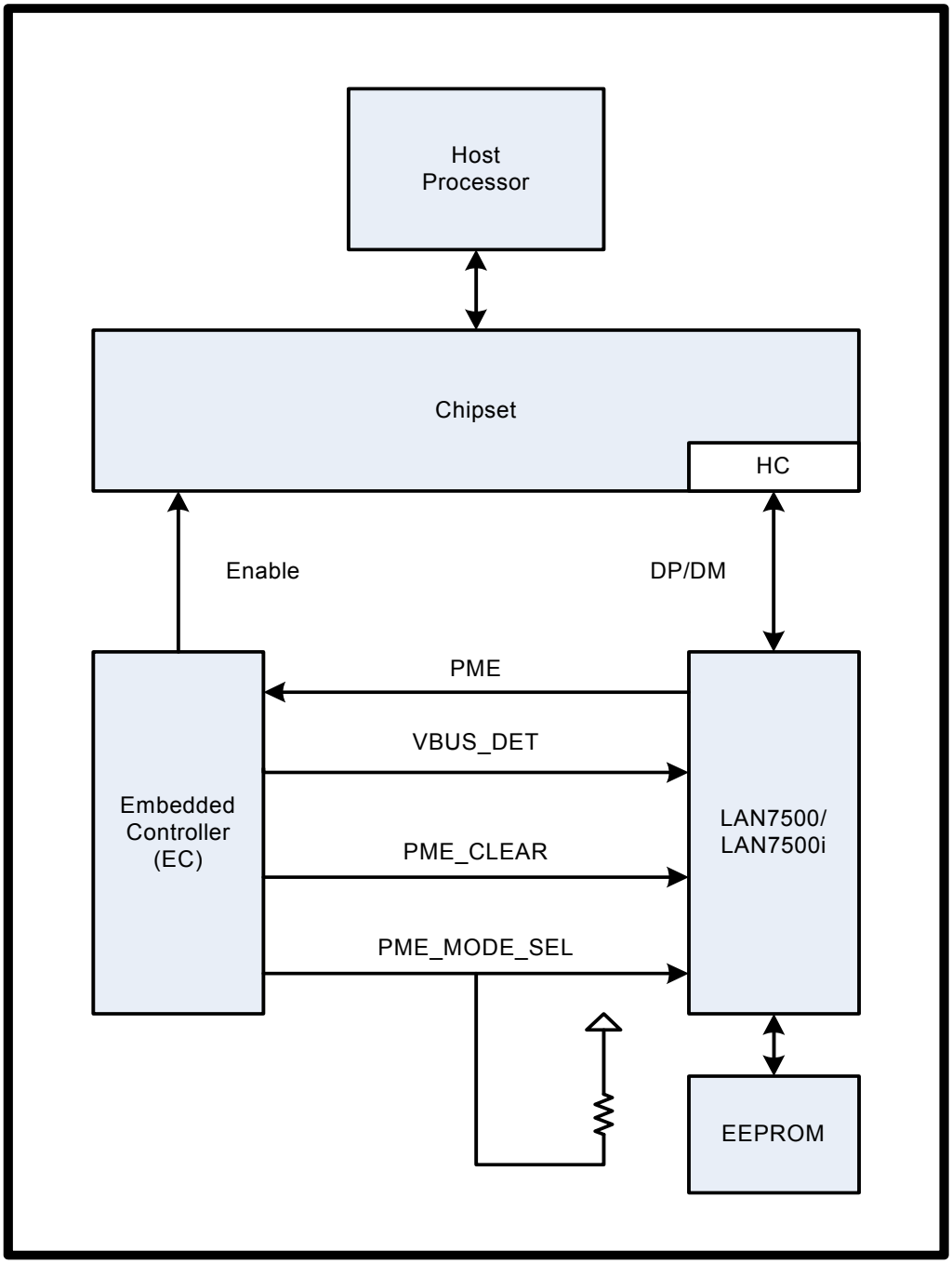
EEPROM Address	EEPROM Contents (Hex)	Description
73h	01	Descriptor Type (Device Descriptor - 01h)
74h - 75h	00 02	USB Specification Number that the device complies with (0200h)
76h	FF	Class Code
77h	00	Subclass Code
78h	FF	Protocol Code
79h	40	Maximum Packet Size for Endpoint 0
7Ah - 7Bh	24 04	Vendor ID (0424h)
7Ch - 7Dh	00 75	Product ID (7500h)
7Eh - 7Fh	00 01	Device Release Number (0100h)
80h	01	Index of Manufacturer String Descriptor
81h	02	Index of Product String Descriptor
82h	03	Index of Serial Number String Descriptor
83h	01	Number of Possible Configurations
84h	09	Size of Full-Speed Configuration Descriptor in bytes (9 bytes)
85h	02	Descriptor Type (Configuration Descriptor - 02h)
86h - 87h	27 00	Total length in bytes of data returned (0027h = 39 bytes)
88h	01	Number of Interfaces
89h	01	Value to use as an argument to select this configuration
8Ah	00	Index of String Descriptor describing this configuration
8Bh	A0	Bus powered and remote wakeup enabled
8Ch	FA	Maximum Power Consumption is 500 mA
8Dh	09	Size of Full-Speed Interface Descriptor in Bytes (9 Bytes)
8Eh	04	Descriptor Type (Interface Descriptor - 04h)
8Fh	00	Number identifying this Interface
90h	00	Value used to select alternative setting
91h	03	Number of Endpoints used for this interface (Less endpoint 0)
92h	FF	Class Code
93h	00	Subclass Code
94h	FF	Protocol Code
95h	00	Index of String Descriptor Describing this interface
96h - FFh	-	Data storage for use by Host as desired

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4.0 PME OPERATION

LAN7500/LAN7500i provides a mechanism for waking up a host system via PME mode of operation. PME signaling is only available while the device is operating in the self powered mode and a properly configured EEPROM is attached. Figure 4-1 illustrates a typical application.

FIGURE 4-1: TYPICAL APPLICATION



The Host Processor is connected to a Chipset containing the Host USB Controller (HC). The USB Host Controller interfaces to LAN7500/LAN7500i via the DP/DM USB signals. An Embedded Controller (EC) signals the Chipset and the Host processor to power up via an Enable signal. The EC interfaces to LAN7500/LAN7500i via four signals. The PME signal is an input to the EC from the device that indicates the occurrence of a wakeup event. The VBUS_DET output of the EC is used to indicate bus power availability. The PME_CLEAR (nRESET) signal is used to clear the PME. The PME_MODE_SEL signal is sampled by the device when PME_CLEAR (nRESET) is asserted and is used by the device to determine whether it should remain in PME mode or resume normal operation.

GPIO pins are used for PME handling. GPIO5 is reserved for use as an output to signal the PME. GPIO6 is reserved for use as the PME_MODE_SEL input.

The application scenario in Figure 4-1 assumes that the Host Processor and the Chipset are powered off, the EC is operational, and the device is in PME mode, waiting for a wake event to occur. A wake event will result in the device signaling a PME event to the EC, which will then wake up the Host Processor and Chipset via the Enable signal. The EC asserts VBUS_DET after the USB bus is powered, sets PME_MODE_SEL to determine whether the device is to begin normal operation or continue in PME mode, and asserts PME_CLEAR (nRESET) to clear the PME.

The following wake events are supported:

- Wakeup Pin(s)

  The GPIO pins not reserved for PME handling have the capability to wake up the device when operating in PME mode. In order for a GPIO to generate a wake event, it's enable bit must be set

  in the GPI0[11:8] Wakeup Enables or GPIO[7:0] Wakeup Enables bytes of the EEPROM, as appropriate. During PME mode of operation, the GPIOs used for signaling (GPIO5 and GPIO6) are not affected by the values set in the corresponding bits of GPIO[7:0] Wakeup Enables.

  GPIOs 0 - 4 and 7 - 10 are available as wakeup pins in PME mode of operation and are active low by default.

- Magic Packet

  Reception of a Magic Packet when in PME mode will result in a PME being asserted.

- Perfect DA match of Physical address

  Reception of an Ethernet frame whose Destination address matches the device's MAC address will result in a PME being asserted.

- PHY Link Up

  Detection of a PHY link partner when in PME mode will result in a PME being asserted.

In order to facilitate PME mode of operation, the GPIO PME Enable bit in the GPIO PME Flags field, must be set and all remaining GPIO PME Flags field bits must be appropriately configured for pulse or level signaling, buffer type, and GPIO PME WOL selection. The PME event is signaled on GPIO5.

The PME_MODE_SEL pin (GPIO6) must be driven to the value that determines whether or not the device remains in PME mode of operation (1) or resumes normal operation (0) when the PME is recognized and cleared by the EC via PME_CLEAR (nRESET) assertion.

Note: When in PME mode or nRESET will always cause the contents of the EEPROM to be reloaded.

Figure 4-2 flowcharts PME operation while in Internal PHY mode. The following conditions hold:

EEPROM Configuration:

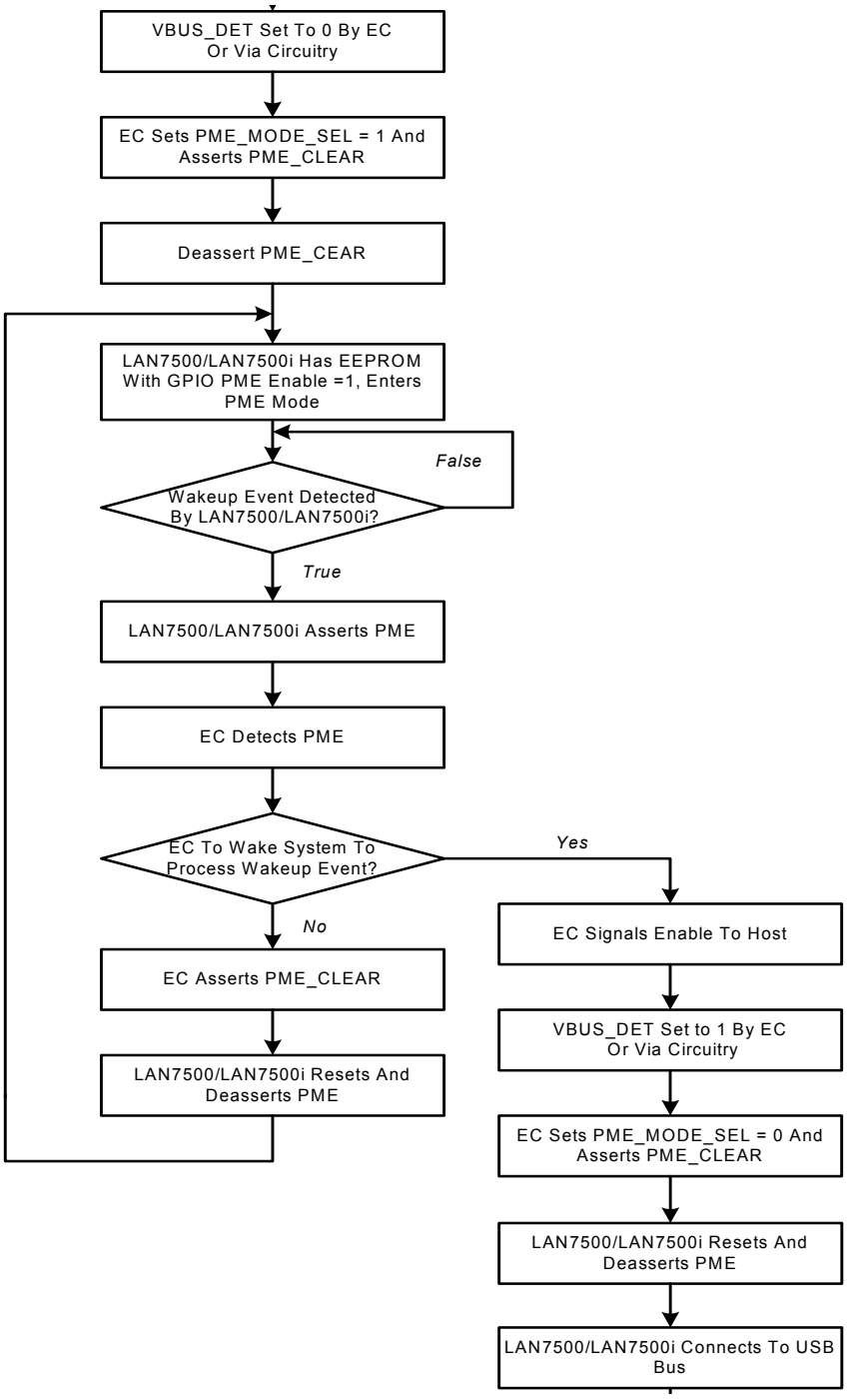
- GPIO PME Enable = 1 (enabled)
- GPIO PME Configuration = 0 (PME signaled via level on GPIO5 pin)
- GPIO PME Length = 0 (NA)
- GPIO PME Polarity = 1 (high level signals event)
- GPIO PME Buffer Type = 1 (Push-Pull)
- GPIO PME WOL Select = 0 (Magic Packet wakeup)
- Power Method = 1 (self powered)
- MAC address for Magic Packet

PME signaling configuration:

- GPIO5 signals PME
- GPIO6 is PME_MODE_SEL

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FIGURE 4-2: PME OPERATION



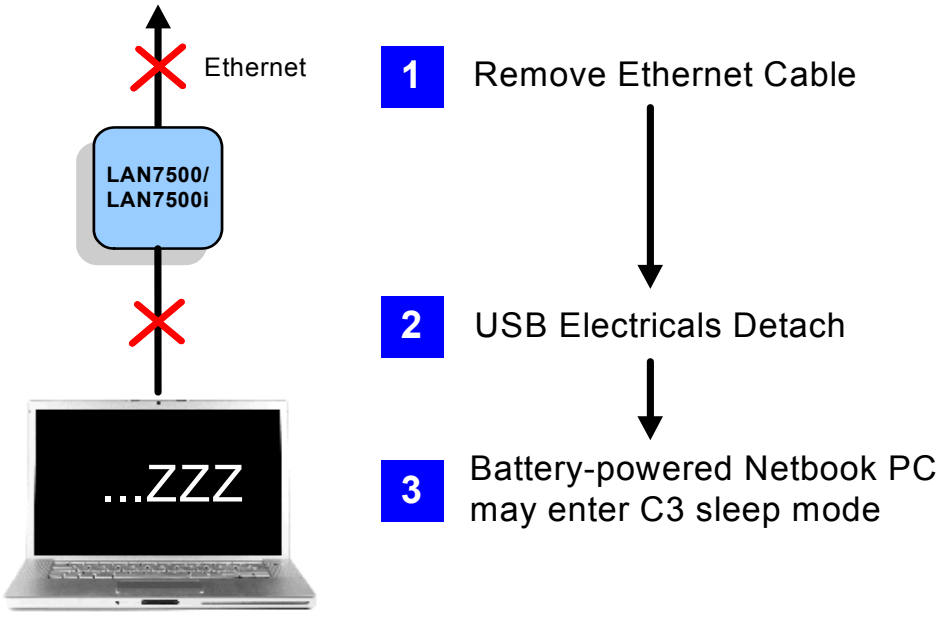
5.0 NETDETACH OPERATION

5.1 NetDetach

NetDetach is a mode of operation where the device detaches from the USB bus after the Ethernet cable is disconnected. This is advantageous for mobile devices, as an attached USB device may prevent the Host CPU from entering the ACPI C3 state. Allowing the CPU to enter the C3 state maximizes battery life, as the C3 state is the lowest of the four APCI power states.

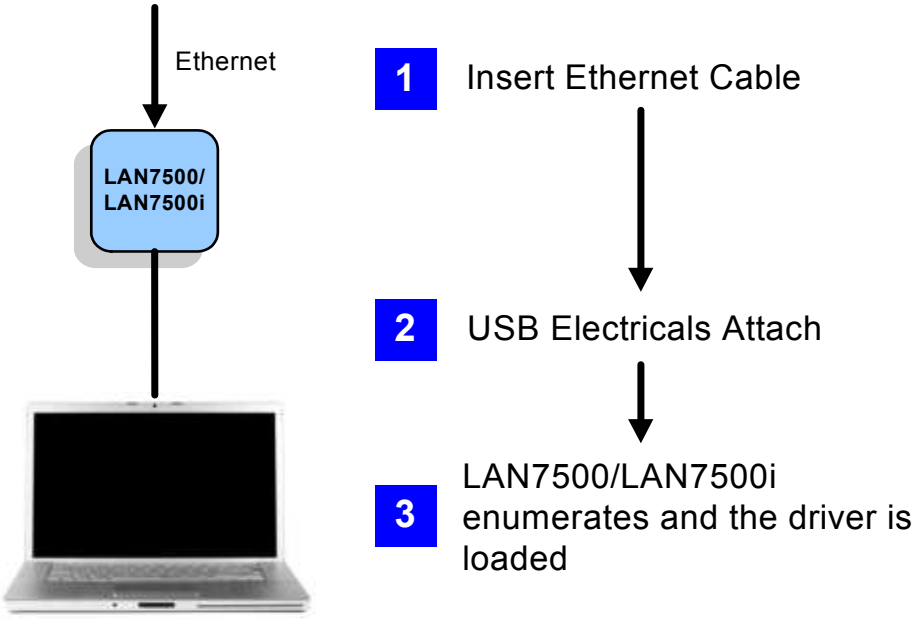
When detached, the device is in a low power state. After the Ethernet cable is reconnected, or a programmed GPIO pin asserts, the device automatically attaches to the USB bus.

FIGURE 5-1: LAN7500/LAN7500I DETACH



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FIGURE 5-2: LAN7500/LAN7500I ATTACH



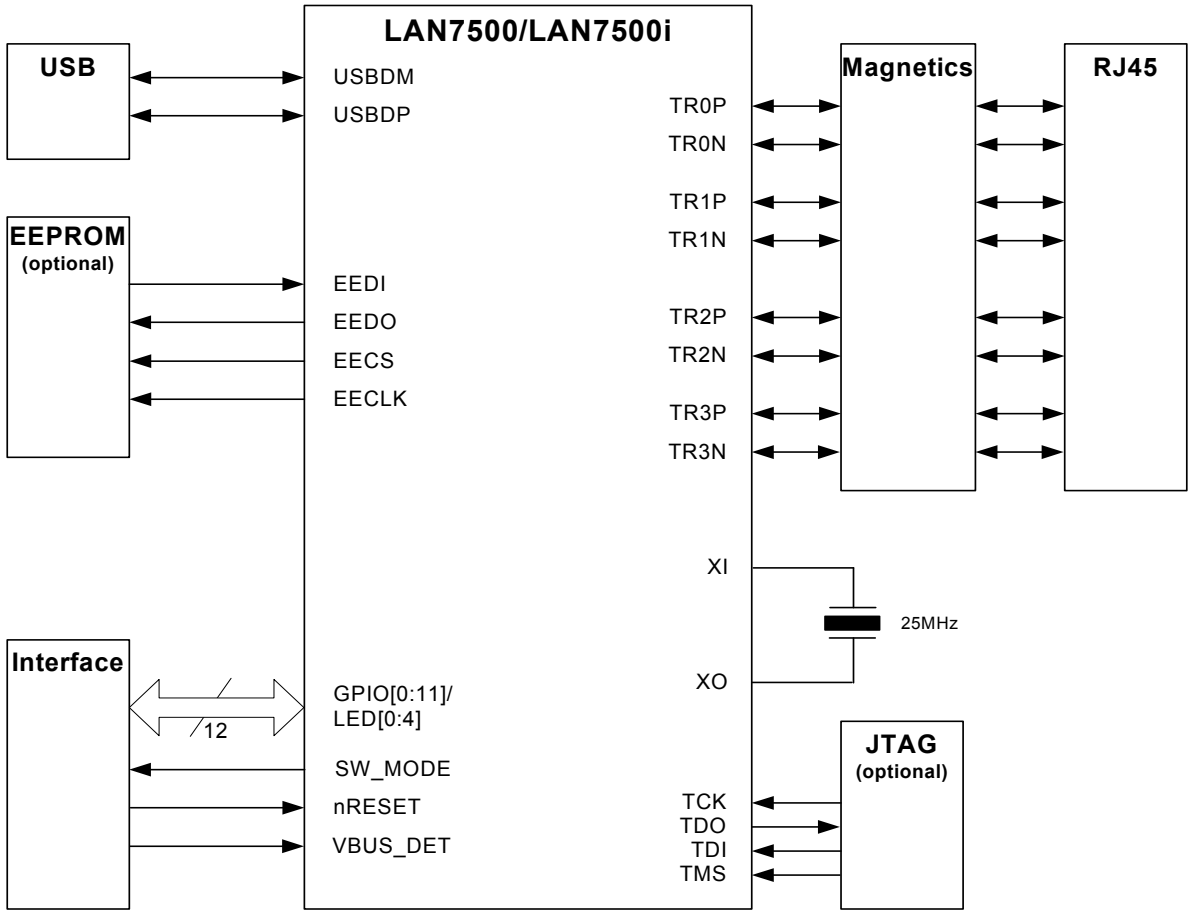
6.0 APPLICATION DIAGRAMS

This section provides typical application diagrams for the following:

- Simplified Application Diagram
- Power Supply & Twisted Pair Interface Diagram

6.1 Simplified Application Diagram

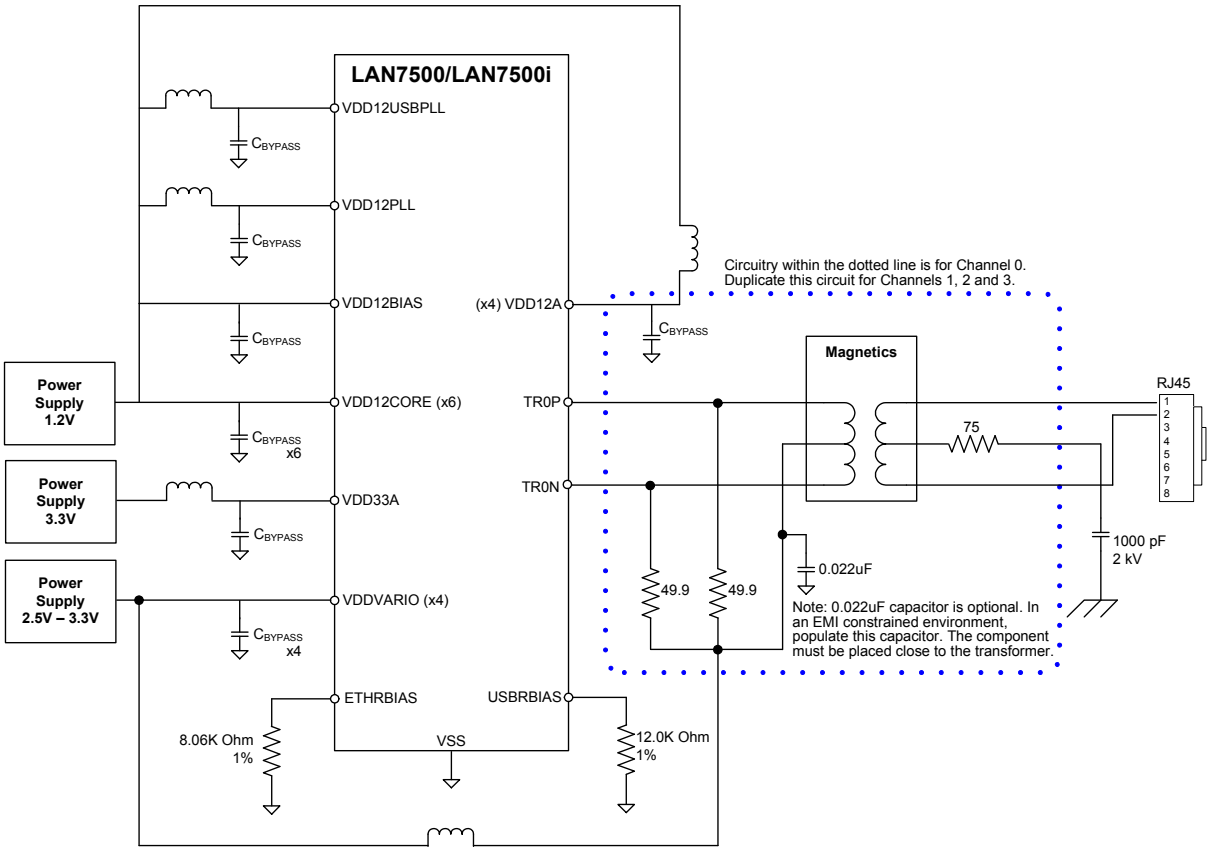
FIGURE 6-1: SIMPLIFIED APPLICATION DIAGRAM



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6.2 Power Supply & Twisted Pair Interface Diagram

FIGURE 6-2: POWER SUPPLY & TWISTED PAIR INTERFACE DIAGRAM



7.0 OPERATIONAL CHARACTERISTICS

7.1 Absolute Maximum Ratings*

Supply Voltage (VDDVARIO) (Note 7-1) . . . . . -0.5V to +3.6V

Analog Supply Voltage (VDD12A) (Note 7-1). . . . . -0.5V to +1.5V

Analog USB Supply Voltage (VDD33A) (Note 7-1) . . . . . -0.5V to +3.6V

Digital Core Supply Voltage (VDD12CORE) (Note 7-1). . . . . -0.5V to +1.5V

Ethernet Magnetics Supply Voltage . . . . . -0.5V to +3.6V

Positive voltage on signal pins, with respect to ground (Note 7-2). . . . . +6.0V

Negative voltage on signal pins, with respect to ground (Note 7-3). . . . . -0.5V

Positive voltage on XI, with respect to ground . . . . . +3.6V

Positive voltage on XO, with respect to ground . . . . . +2.5V

Ambient Operating Temperature in Still Air (T_A). . . . . Note 7-4

Junction to Ambient (θ_{JA}). 24.4ºC/W

Junction to Top of Package (Ψ_{JT}) 0.1ºC/W

Storage Temperature . . . . . -55ºC to +150ºC

Lead Temperature Range . . . . . Refer to JEDEC Spec. J-STD-020

HBM ESD Performance . . . . . JEDEC Class 3A

Latch-up Performance per EIA/JESD 78 . . . . . ±150mA

Note 7-1 When powering this device from laboratory or system power supplies, it is important that the absolute maximum ratings not be exceeded or device failure can result. Some power supplies exhibit voltage spikes on their outputs when AC power is switched on or off. In addition, voltage transients on the AC power line may appear on the DC output. If this possibility exists, it is suggested that a clamp circuit be used.

Note 7-2 This rating does not apply to the following pins: XI, XO, ETHRBIAS, USBRBIAS.

Note 7-3 This rating does not apply to the following pins: ETHRBIAS, USBRBIAS.

Note 7-4 0ºC to +70ºC for commercial version, -40ºC to +85ºC for industrial version.

*Stresses exceeding those listed in this section could cause permanent damage to the device. This is a stress rating only. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Functional operation of the device at any condition exceeding those indicated in Section 7.2, "Operating Conditions**", Section 7.4, "DC Specifications", or any other applicable section of this specification is not implied. Note, device signals are *NOT* 5 volt tolerant unless specified otherwise.

7.2 Operating Conditions**

Supply Voltage (VDDVARIO) . . . . . +2.25V to +3.6V

Supply Voltage (VDD12A) . . . . . +1.14V to +1.26V

Analog USB Supply Voltage (VDD33A) . . . . . +3.0V to +3.6V

Digital Core Supply Voltage (VDD12CORE) . . . . . +1.14V to +1.26V

Ethernet Magnetics Supply Voltage . . . . . +2.25V to +3.6V

Ambient Operating Temperature in Still Air (T_A). . . . . Note 7-4

**Proper operation of the device is guaranteed only within the ranges specified in this section. After the device has completed power-up, VDDVARIO and the magnetics power supply must maintain their voltage level with ±10%. Varying the voltage greater than ±10% after the device has completed power-up can cause errors in device operation.

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7.3 Power Consumption

This section details the power consumption of the device as measured during various modes of operation. For each mode of operation, two tables are provided: one for operation of VDDVARIO (and magnetics) at 2.5V, and the other for operation of VDDVARIO (and magnetics) at 3.3V. Power consumption values are provided for both the device-only, and for the device plus Ethernet components. Power dissipation is determined by temperature, supply voltage, and external source/sink requirements.

7.3.1 SUSPEND0

7.3.1.1 VDDVARIO & Magnetics = 2.5V

TABLE 7-1: SUSPEND0 CURRENT & POWER (VDDVARIO & MAGNETICS = 2.5V)

Parameter	Min	Typical	MAX	Unit
Supply current (VDD33A = 3.3V)		0.4		mA
Supply current (VDDVARIO = 2.5V)		3.1		mA
Supply current (VDD12CORE, VDD12BIAS, VDD12USBPLL, VDD12PLL, VDD12A = 1.2V)		453		mA
Power Dissipation (Device Only)		553		mW
Power Dissipation (Device and Ethernet components)		1047		mW

7.3.1.2 VDDVARIO & Magnetics = 3.3V

TABLE 7-2: SUSPEND0 CURRENT & POWER (VDDVARIO & MAGNETICS = 3.3V)

Parameter	Min	Typical	MAX	Unit
Supply current (VDDVARIO, VDD33A = 3.3V)		3.5		mA
Supply current (VDD12CORE, VDD12BIAS, VDD12USBPLL, VDD12PLL, VDD12A = 1.2V)		453		mA
Power Dissipation (Device Only)		556		mW
Power Dissipation (Device and Ethernet components)		1231		mW

7.3.2 SUSPEND1

7.3.2.1 VDDVARIO & Magnetics = 2.5V

TABLE 7-3: SUSPEND1 CURRENT & POWER (VDDVARIO & MAGNETICS = 2.5V)

Parameter	Min	Typical	MAX	Unit
Supply current (VDD33A = 3.3V)		0.5		mA
Supply current (VDDVARIO = 2.5V)		0.3		mA
Supply current (VDD12CORE, VDD12BIAS, VDD12USBPLL, VDD12PLL, VDD12A = 1.2V)		35		mA
Power Dissipation (Device Only)		44		mW
Power Dissipation (Device and Ethernet components)		82		mW

7.3.2.2 VDDVARIO & Magnetics = 3.3V

TABLE 7-4: SUSPEND1 CURRENT & POWER (VDDVARIO & MAGNETICS = 3.3V)

Parameter	Min	Typical	MAX	Unit
Supply current (VDDVARIO, VDD33A = 3.3V)		0.8		mA
Supply current (VDD12CORE, VDD12BIAS, VDD12USBPLL, VDD12PLL, VDD12A = 1.2V)		35		mA
Power Dissipation (Device Only)		44		mW
Power Dissipation (Device and Ethernet components)		114		mW

7.3.3 SUSPEND2 (SELF-POWERED)

7.3.3.1 VDDVARIO & Magnetics = 2.5V

TABLE 7-5: SUSPEND2 (SELF-POWERED) CURRENT & POWER (VDDVARIO & MAGNETICS = 2.5V)

Parameter	Min	Typical	MAX	Unit
Supply current (VDD33A = 3.3V)		0.5		mA
Supply current (VDDVARIO = 2.5V)		0.2		mA
Supply current (VDD12CORE, VDD12BIAS, VDD12USBPLL, VDD12PLL, VDD12A = 1.2V)	n	2.0		mA
Power Dissipation (Device Only)		4.4		mW
Power Dissipation (Device and Ethernet components)		4.5		mW

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7.3.3.2 VDDVARIO & Magnetics = 3.3V

TABLE 7-6: SUSPEND2 (SELF-POWERED) CURRENT & POWER (VDDVARIO & MAGNETICS = 3.3V)

Parameter	Min	Typical	MAX	Unit
Supply current (VDDVARIO, VDD33A = 3.3V)		0.7		mA
Supply current (VDD12CORE, VDD12BIAS, VDD12USBPLL, VDD12PLL, VDD12A = 1.2V)		2.0		mA
Power Dissipation (Device Only)		4.6		mW
Power Dissipation (Device and Ethernet components)		4.6		mW

7.3.4 SUSPEND2 (BUS-POWERED)

7.3.4.1 VDDVARIO & Magnetics = 2.5V

TABLE 7-7: SUSPEND2 (BUS-POWERED) CURRENT & POWER (VDDVARIO & MAGNETICS = 2.5V)

Parameter	Min	Typical	MAX	Unit
Supply current (VDD33A = 3.3V)		0.5		mA
Supply current (VDDVARIO = 2.5V)		0.2		mA
Supply current (VDD12CORE, VDD12BIAS, VDD12USBPLL, VDD12PLL, VDD12A = 1.2V)		1.0		mA
Power Dissipation (Device Only)		3.3		mW
Power Dissipation (Device and Ethernet components)		3.3		mW

7.3.4.2 VDDVARIO & Magnetics = 3.3V

TABLE 7-8: SUSPEND2 (BUS-POWERED) CURRENT & POWER (VDDVARIO & MAGNETICS = 3.3V)

Parameter	Min	Typical	MAX	Unit
Supply current (VDDVARIO, VDD33A = 3.3V)		0.7		mA
Supply current (VDD12CORE, VDD12BIAS, VDD12USBPLL, VDD12PLL, VDD12A = 1.2V)		1.0		mA
Power Dissipation (Device Only)		3.4		mW
Power Dissipation (Device and Ethernet components)		3.5		mW

7.3.5 OPERATIONAL

7.3.5.1 VDDVARIO & Magnetics = 2.5V

TABLE 7-9: OPERATIONAL CURRENT & POWER (VDDVARIO & MAGNETICS = 2.5V)

Parameter	Min	Typical	MAX	Unit
1000BASE-T Full Duplex (USB High-Speed)				
Supply current (VDD33A = 3.3V)		6.8		mA
Supply current (VDDVARIO = 2.5V)		3.1		mA
Supply current (VDD12CORE, VDD12BIAS, VDD12USBPLL, VDD12PLL, VDD12A = 1.2V)		489		mA
Power Dissipation (Device Only)		617		mW
Power Dissipation (Device and Ethernet components)		1113		mW
100BASE-TX Full Duplex (USB High-Speed)				
Supply current (VDD33A = 3.3V)		6.6		mA
Supply current (VDDVARIO = 2.5V)		0.9		mA
Supply current (VDD12CORE, VDD12BIAS, VDD12USBPLL, VDD12PLL, VDD12A = 1.2V)		119		mA
Power Dissipation (Device Only)		167		mW
Power Dissipation (Device and Ethernet components)		311		mW
10BASE-T Full Duplex (USB High-Speed)				
Supply current (VDD33A = 3.3V)		5.6		mA
Supply current (VDDVARIO = 2.5V)		0.8		mA
Supply current (VDD12CORE, VDD12BIAS, VDD12USBPLL, VDD12PLL, VDD12A = 1.2V)		66		mA
Power Dissipation (Device Only)		100		mW
Power Dissipation (Device and Ethernet components)		394		mW

7.3.5.2 VDDVARIO & Magnetics = 3.3V

TABLE 7-10: OPERATIONAL CURRENT & POWER (VDDVARIO & MAGNETICS = 3.3V)

Parameter	Min	Typical	MAX	Unit
1000BASE-T Full Duplex (USB High-Speed)				
Supply current (VDDVARIO, VDD33A = 3.3V)		9.8		mA
Supply current (VDD12CORE, VDD12BIAS, VDD12USBPLL, VDD12PLL, VDD12A = 1.2V)		489		mA
Power Dissipation (Device Only)		620		mW
Power Dissipation (Device and Ethernet components)		1296		mW

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TABLE 7-10: OPERATIONAL CURRENT & POWER (VDDVARIO & MAGNETICS = 3.3V)

Parameter	Min	Typical	MAX	Unit
100BASE-TX Full Duplex (USB High-Speed)				
Supply current (VDDVARIO, VDD33A = 3.3V)		7.5		mA
Supply current (VDD12CORE, VDD12BIAS, VDD12USBPLL, VDD12PLL, VDD12A = 1.2V)		119		mA
Power Dissipation (Device Only)		168		mW
Power Dissipation (Device and Ethernet components)		379		mW
10BASE-T Full Duplex (USB High-Speed)				
Supply current (VDDVARIO, VDD33A = 3.3V)		6.4		mA
Supply current (VDD12CORE, VDD12BIAS, VDD12USBPLL, VDD12PLL, VDD12A = 1.2V)		66		mA
Power Dissipation (Device Only)		101		mW
Power Dissipation (Device and Ethernet components)		512		mW

7.4 DC Specifications

TABLE 7-11: I/O BUFFER CHARACTERISTICS

Parameter	Symbol	Min	2.5V TYP	3.3V TYP	MAX	UNITS	NOTES
VIS Type Input Buffer							
Low Input Level	V_{ILI}	-0.3				V	
High Input Level	V_{IHI}				3.6	V	
Negative-Going Threshold	V_{ILT}	0.64	1.15	1.41	1.76	V	Schmitt trigger
Positive-Going Threshold	V_{IHT}	0.81	1.29	1.65	1.90	V	Schmitt trigger
SchmittTrigger Hysteresis (V_{IHT} - V_{ILT})	V_{HYS}	102	136	138	288	mV	
Input Leakage (V_{IN} = VSS or VDDVARIO)	I_{IH}	-10			10	uA	Note 7-5
Input Capacitance	C_{IN}				3	pF	
IS_5V Type Input Buffer							
Low Input Level	V_{ILI}	-0.3	N/A			V	
High Input Level	V_{IHI}		N/A		5.5	V	
Negative-Going Threshold	V_{ILT}	1.01	N/A	1.19	1.39	V	Schmitt trigger
Positive-Going Threshold	V_{IHT}	1.39	N/A	1.59	1.79	V	Schmitt trigger
SchmittTrigger Hysteresis (V_{IHT} - V_{ILT})	V_{HYS}	336	N/A	399	459	mV	
Input Leakage (V_{IN} = VSS or VDDVARIO)	I_{IH}	-10			10	uA	Note 7-5
Input Leakage (V_{IN} = 5.5V)	I_{IH}				35	uA	Note 7-5, Note 7-6
Input Capacitance	C_{IN}				3	pF	
VO6 Type Buffers							
Low Output Level	V_{OL}				0.4	V	I_{OL} = 6mA
High Output Level	V_{OH}	VDDVARIO - 0.4				V	I_{OH} = -6mA
VOD6 Type Buffer							
Low Output Level	V_{OL}				0.4	V	I_{OL} = 6mA
VO8 Type Buffers							
Low Output Level	V_{OL}				0.4	V	I_{OL} = 8mA
High Output Level	V_{OH}	VDDVARIO - 0.4				V	I_{OH} = -8mA
VOD8 Type Buffer							
Low Output Level	V_{OL}				0.4	V	I_{OL} = 8mA
ICLK Type Buffer (XI Input)							Note 7-7
Low Input Level	V_{ILI}	-0.3			0.5	V	
High Input Level	V_{IHI}	0.9			3.6	V	

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Note 7-5 This specification applies to all inputs and tri-stated bi-directional pins. Internal pull-down and pull-up resistors add ±50 uA per-pin (typical).

Note 7-6 This is the total 5.5V input leakage for the entire device.

Note 7-7 XI can optionally be driven from a 25 MHz single-ended clock oscillator.

TABLE 7-12: 1000BASE-T TRANSCEIVER CHARACTERISTICS

Parameter	Symbol	Min	Typ	Max	Units	Notes
Peak Differential Output Voltage	V_{OP}	670		820	mV	Note 7-8
Signal Amplitude Symmetry	V_{SS}			1	%	Note 7-8
Signal Scaling	V_{SC}			2	%	Note 7-9
Output Droop	V_{OD}	73.1			%	Note 7-8
Transmission Distortion				10	mV	Note 7-10

Note 7-8 IEEE 802.ab Test Mode 1

Note 7-9 From 1/2 of average V_{OP}, Test Mode 1

Note 7-10 IEEE 802.ab distortion processing

TABLE 7-13: 100BASE-TX TRANSCEIVER CHARACTERISTICS

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
Peak Differential Output Voltage High	V_{PPH}	950	-	1050	mVpk	Note 7-11
Peak Differential Output Voltage Low	V_{PPL}	-950	-	-1050	mVpk	Note 7-11
Signal Amplitude Symmetry	V_{SS}	98	-	102	%	Note 7-11
Signal Rise and Fall Time	T_{RF}	3.0	-	5.0	nS	Note 7-11
Rise and Fall Symmetry	T_{RFS}	-	-	0.5	nS	Note 7-11
Duty Cycle Distortion	D_{CD}	35	50	65	%	Note 7-12
Overshoot and Undershoot	V_{OS}	-	-	5	%	
Jitter				1.4	nS	Note 7-13

Note 7-11 Measured at line side of transformer, line replaced by 100Ω (±1%) resistor.

Note 7-12 Offset from 16nS pulse width at 50% of pulse peak.

Note 7-13 Measured differentially.

TABLE 7-14: 10BASE-T TRANSCEIVER CHARACTERISTICS

PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
Transmitter Peak Differential Output Voltage	V_{OUT}	2.2	2.5	2.8	V	Note 7-14
Receiver Differential Squelch Threshold	V_{DS}	300	420	585	mV	

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Note 7-14 Min/max voltages guaranteed as measured with 100Ω resistive load.

7.5 AC Specifications

This section details the various AC timing specifications of the device.

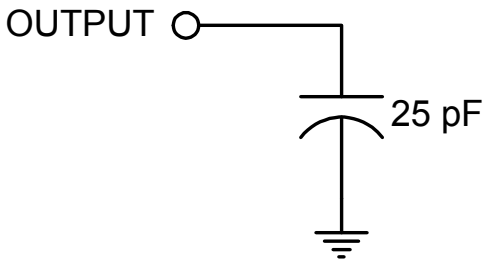
Note: The USBDP and USBDM pin timing adheres to the USB 2.0 specification. Refer to the Universal Serial Bus Revision 2.0 specification for detailed USB timing information.

Note: The Ethernet TX/RX pin timing adheres to the IEEE 802.3 specification. Refer to the IEEE 802.3 specification for detailed Ethernet timing information.

7.5.1 EQUIVALENT TEST LOAD

Output timing specifications assume the 25pF equivalent test load illustrated in Figure 7-1 below, unless otherwise specified.

FIGURE 7-1: OUTPUT EQUIVALENT TEST LOAD



7.5.2 POWER SEQUENCE TIMING

Power supplies must adhere to the following rules:

- All power supplies of the same voltage must be powered up/down together.
- There is no power-up sequencing requirement, however all power supplies must reach operational levels within the time periods specified in Table 7-15.
- There is no power-down sequencing or timing requirement, however the device must not be powered for an extended period of time without all supplies at operational levels.
- Following initial power-on, or if a power supply brownout occurs (i.e., one or more supplies drops below operational limits), a power-on reset must be executed once all power supplies reach operational levels. Refer to Section 7.5.3, "Power-On Reset Timing," on page 43 for power-on reset requirements.
- With the exception of VBUS_DET, do not drive input signals without power supplied to the device.

Note: Violation of these specifications may damage the device.

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FIGURE 7-2: POWER SEQUENCE TIMING

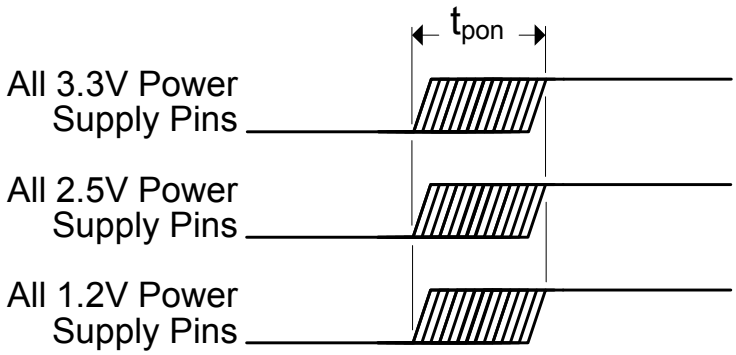


TABLE 7-15: POWER SEQUENCE TIMING VALUES

SYMBOL	DESCRIPTION	MIN	TYP	MAX	UNITS
t_{pon}	Power supply turn on time	0		25	mS

Note: The VDDVARIO power supply can be run at 2.5V or 3.3V.

Note: The magnetics power supply can be run at 2.5V or 3.3V.

7.5.3 POWER-ON RESET TIMING

Figure 7-3 illustrates the nRESET timing requirements in relation to power-on. A hardware reset (nRESET assertion) is required following power-on. For proper operation, nRESET must be asserted for no less than t_{rstia}. The nRESET pin can be asserted at any time, but must not be deasserted before t_{purstd} after all external power supplies have reached operational levels.

FIGURE 7-3: NRESET POWER-ON TIMING

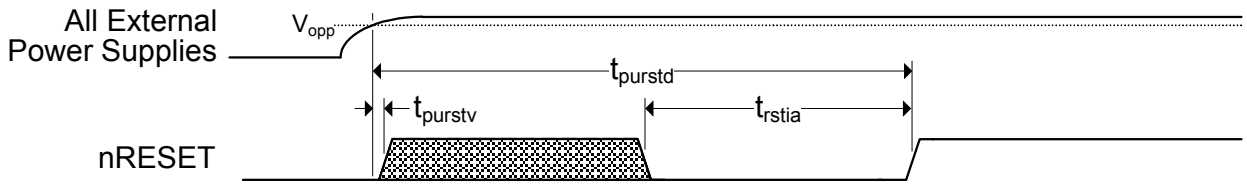


TABLE 7-16: NRESET POWER-ON TIMING VALUES

SYMBOL	DESCRIPTION	MIN	TYP	MAX	UNITS
t_{purstd}	External power supplies at operational level to nRESET deassertion	25			mS
t_{purstv}	External power supplies at operational level to nRESET valid	0			nS
t_{rstia}	nRESET input assertion time	100			µS

Note: nRESET deassertion must be monotonic.

7.5.4 RESET TIMING

Figure 7-3 illustrates the nRESET pin timing requirements. When used, nRESET must be asserted for no less than t_{rstia}.

Note: A hardware reset (nRESET assertion) is required following power-on. Refer to Section 7.5.3, "Power-On Reset Timing," on page 43 for additional information.

FIGURE 7-4: NRESET TIMING

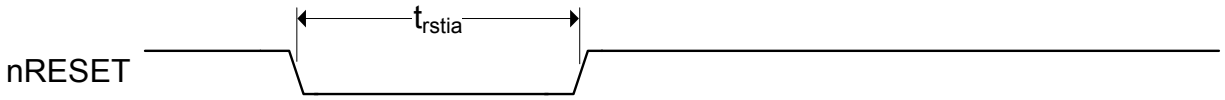


TABLE 7-17: NRESET TIMING VALUES

SYMBOL	DESCRIPTION	MIN	TYP	MAX	UNITS
t_{rstia}	nRESET input assertion time	1			µS

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7.5.5 EEPROM TIMING

The following specifies the EEPROM timing requirements for the device:

FIGURE 7-5: EEPROM TIMING

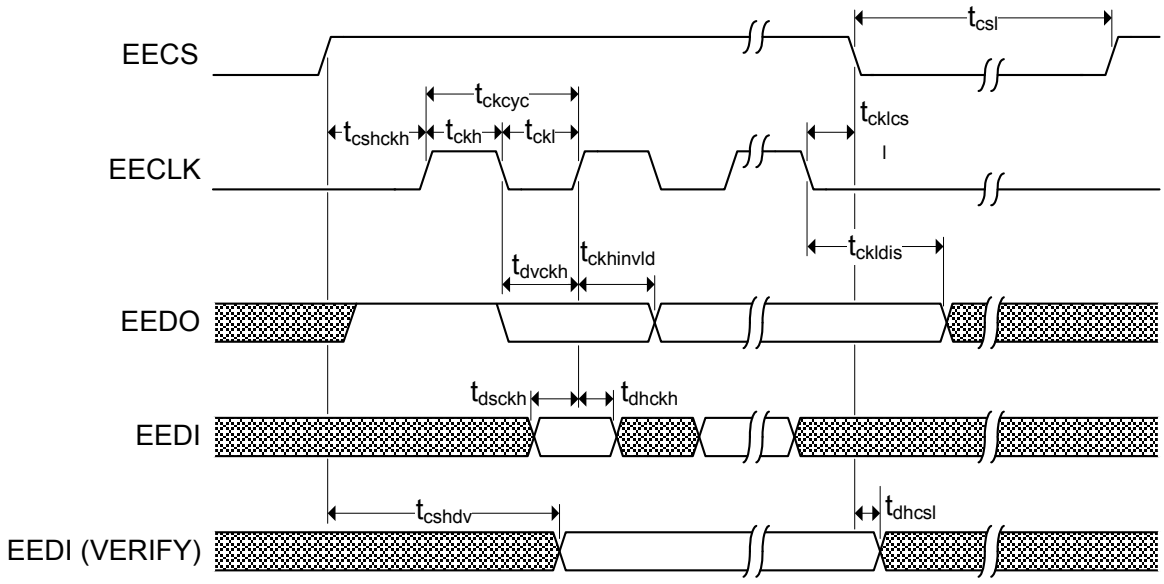


TABLE 7-18: EEPROM TIMING VALUES

SYMBOL	DESCRIPTION	MIN	TYP	MAX	UNITS
t_{ckcyc}	EECLK Cycle time	1110		1130	ns
t_{ckh}	EECLK High time	550		570	ns
t_{ckl}	EECLK Low time	550		570	ns
t_{cshckh}	EECS high before rising edge of EECLK	1070			ns
t_{cklcsl}	EECLK falling edge to EECS low	30			ns
t_{dvckh}	EEDO valid before rising edge of EECLK	550			ns
$t_{ckhinvld}$	EEDO invalid after rising edge EECLK	550			ns
t_{dsckh}	EEDI setup to rising edge of EECLK	90			ns
t_{dhckh}	EEDI hold after rising edge of EECLK	0			ns
t_{ckldis}	EECLK low to data disable (OUTPUT)	580			ns
t_{cshdv}	EEDIO valid after EECS high (VERIFY)			600	ns
t_{dhcsl}	EEDIO hold after EECS low (VERIFY)	0			ns
t_{csl}	EECS low	1070			ns

7.5.6 JTAG TIMING

This section specifies the JTAG timing of the device. Please refer to Section 1.1.10, "TAP Controller," on page 6 for additional details.

FIGURE 7-6: JTAG TIMING

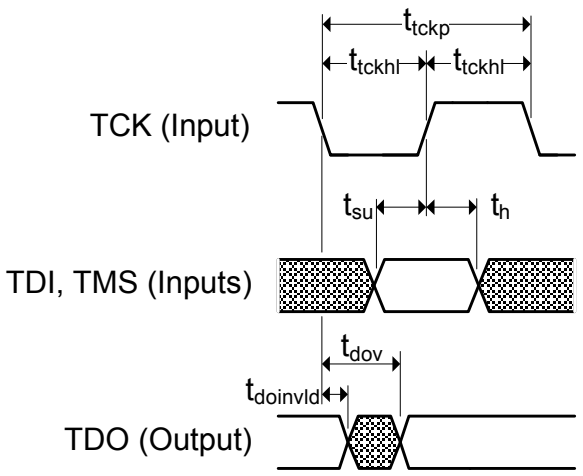


TABLE 7-19: JTAG TIMING VALUES

Symbol	Description	Min	Max	Units	Notes
t_{tckp}	TCK clock period	66.67		ns	
t_{tckhl}	TCK clock high/low time	t_{tckp}*0.4	t_{tckp}*0.6	ns	
t_{su}	TDI, TMS setup to TCK rising edge	10		ns	
t_h	TDI, TMS hold from TCK rising edge	10		ns	
t_{dov}	TDO output valid from TCK falling edge		16	ns	
$t_{doinvld}$	TDO output invalid from TCK falling edge	0		ns	

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7.6 Clock Circuit

The device can accept either a 25 MHz crystal (preferred) or a 25 MHz single-ended clock oscillator (±50 ppm) input. If the single-ended clock oscillator method is implemented, XO should be left unconnected and XI should be driven with a nominal 0-3.3V clock signal. The input clock duty cycle is 40% minimum, 50% typical and 60% maximum.

It is recommended that a crystal utilizing matching parallel load capacitors be used for the crystal input/output signals (XI/XO). Either a 300uW or 100uW 25 MHz crystal may be utilized. The 300uW 25 MHz crystal specifications are detailed in Section 7.6.1, "300uW 25 MHz Crystal Specification," on page 47. The 100uW 25 MHz crystal specifications are detailed in Section 7.6.2, "100uW 25 MHz Crystal Specification," on page 48.

7.6.1 300UW 25 MHZ CRYSTAL SPECIFICATION

When utilizing a 300uW 25 MHz crystal, the following circuit design (Figure 7-7) and specifications (Table 7-20) are required to ensure proper operation.

FIGURE 7-7: 300UW 25 MHZ CRYSTAL CIRCUIT

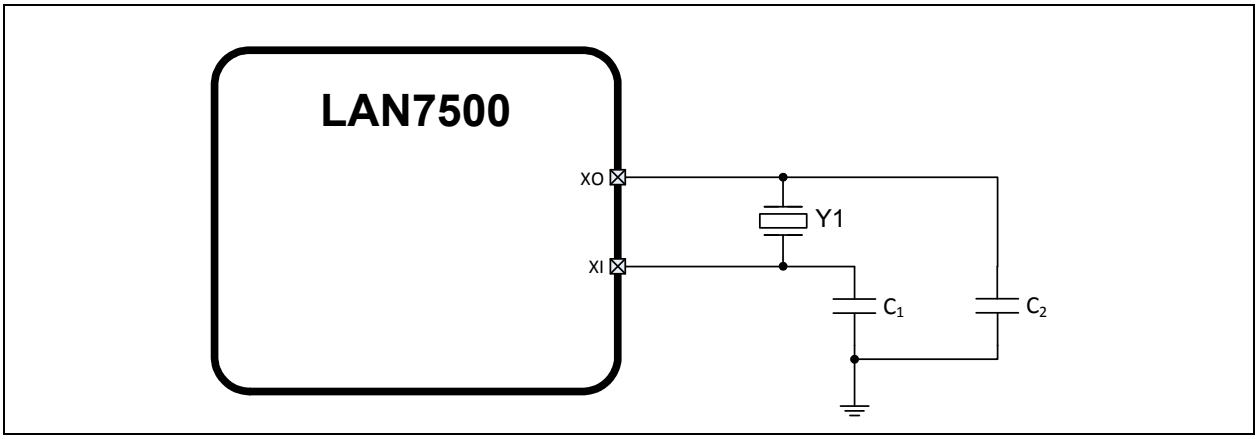


TABLE 7-20: 300UW 25 MHZ CRYSTAL SPECIFICATIONS

PARAMETER	SYMBOL	MIN	NOM	MAX	UNITS	NOTES
Crystal Cut			AT, typ			
Crystal Oscillation Mode			Fundamental Mode			
Crystal Calibration Mode			Parallel Resonant Mode			
Frequency	F_{fund}	-	25.000	-	MHz	
Frequency Tolerance @ 25ºC	F_{tol}	-	-	±50	PPM	Note 7-15
Frequency Stability Over Temp	F_{temp}	-	-	±50	PPM	Note 7-15
Frequency Deviation Over Time	F_{age}	-	±3 to 5	-	PPM	Note 7-16
Total Allowable PPM Budget		-	-	±50	PPM	Note 7-17
Shunt Capacitance	C_O	-	7 typ	-	pF	
Load Capacitance	C_L	-	20 typ	-	pF	
Drive Level	P_W	300	-	-	uW	
Equivalent Series Resistance	R_1	-	-	50	Ohm	
Operating Temperature Range		Note 7-18	-	Note 7-19	ºC	
LAN7500/LAN7500i XI Pin Capacitance		-	3 typ	-	pF	Note 7-20
LAN7500/LAN7500i XO Pin Capacitance		-	3 typ	-	pF	Note 7-20

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Note 7-15 The maximum allowable values for Frequency Tolerance and Frequency Stability are application dependent. Since any particular application must meet the IEEE ±50 PPM Total PPM Budget, the combination of these two values must be approximately ±45 PPM (allowing for aging).

Note 7-16 Frequency Deviation Over Time is also referred to as Aging.

Note 7-17 The total deviation for the Transmitter Clock Frequency is specified by IEEE 802.3u as ±50 PPM.

Note 7-18 0ºC for commercial version, -40ºC for industrial version.

Note 7-19 +70ºC for commercial version, +85ºC for industrial version.

Note 7-20 This number includes the pad, the bond wire and the lead frame. PCB capacitance is not included in this value. The XO/XI pin and PCB capacitance values are required to accurately calculate the value of the two external load capacitors. These two external load capacitors determine the accuracy of the 25.000 MHz frequency.

7.6.2 100UW 25 MHZ CRYSTAL SPECIFICATION

When utilizing a 100uW 25 MHz crystal, the following circuit design (Figure 7-8) and specifications (Table 7-21) are required to ensure proper operation.

FIGURE 7-8: 100UW 25 MHZ CRYSTAL CIRCUIT

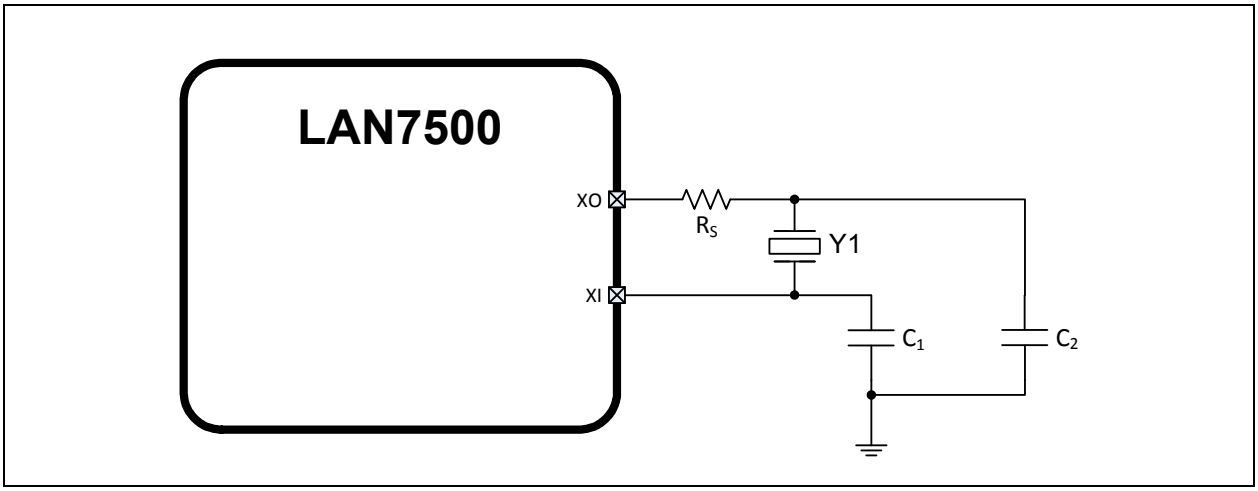


TABLE 7-21: 100UW 25 MHZ CRYSTAL SPECIFICATIONS

Parameter	Symbol	Min	Nom	Max	Units	Notes
Crystal Cut	AT, typ					—
Crystal Oscillation Mode	Fundamental Mode					—
Crystal Calibration Mode	Parallel Resonant Mode					—
Frequency	F_{fund}	—	25.000	—	MHz	—
Frequency Tolerance @ 25ºC	F_{tol}	—	—	±50	PPM	Note 7-21
Frequency Stability Over Temp	F_{temp}	—	—	±50	PPM	Note 7-21
Frequency Deviation Over Time	F_{age}	—	±3 to 5	—	PPM	Note 7-22
Total Allowable PPM Budget	—	—	—	±50	PPM	Note 7-23
Shunt Capacitance	C_O	—	—	5	pF	—
Load Capacitance	C_L	8	—	12	pF	—
Drive Level	P_W	—	100	—	uW	Note 7-24

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TABLE 7-21: 100UW 25 MHZ CRYSTAL SPECIFICATIONS (CONTINUED)

Parameter	Symbol	Min	Nom	Max	Units	Notes
Equivalent Series Resistance	R_1	—	—	80	Ohm	—
LAN7500/LAN7500i XO Series Resistor	R_s	495	500	505	Ohm	—
Operating Temperature Range	—	Note 7-25	—	Note 7-26	ºC	—
LAN7500/LAN7500i XI Pin Capacitance	—	—	3 typ	—	pF	Note 7-27
LAN7500/LAN7500i XO Pin Capacitance	—	—	3 typ	—	pF	Note 7-27

Note 7-21 The maximum allowable values for Frequency Tolerance and Frequency Stability are application dependent. Since any particular application must meet the IEEE ±50 PPM Total PPM Budget, the combination of these two values must be approximately ±45 PPM (allowing for aging).

Note 7-22 Frequency Deviation Over Time is also referred to as Aging.

Note 7-23 The total deviation for the Transmitter Clock Frequency is specified by IEEE 802.3u as ±100 PPM.

Note 7-24 The crystal must support 100uW operation to utilize this circuit.

Note 7-25 0ºC for extended commercial version, -40ºC for industrial version.

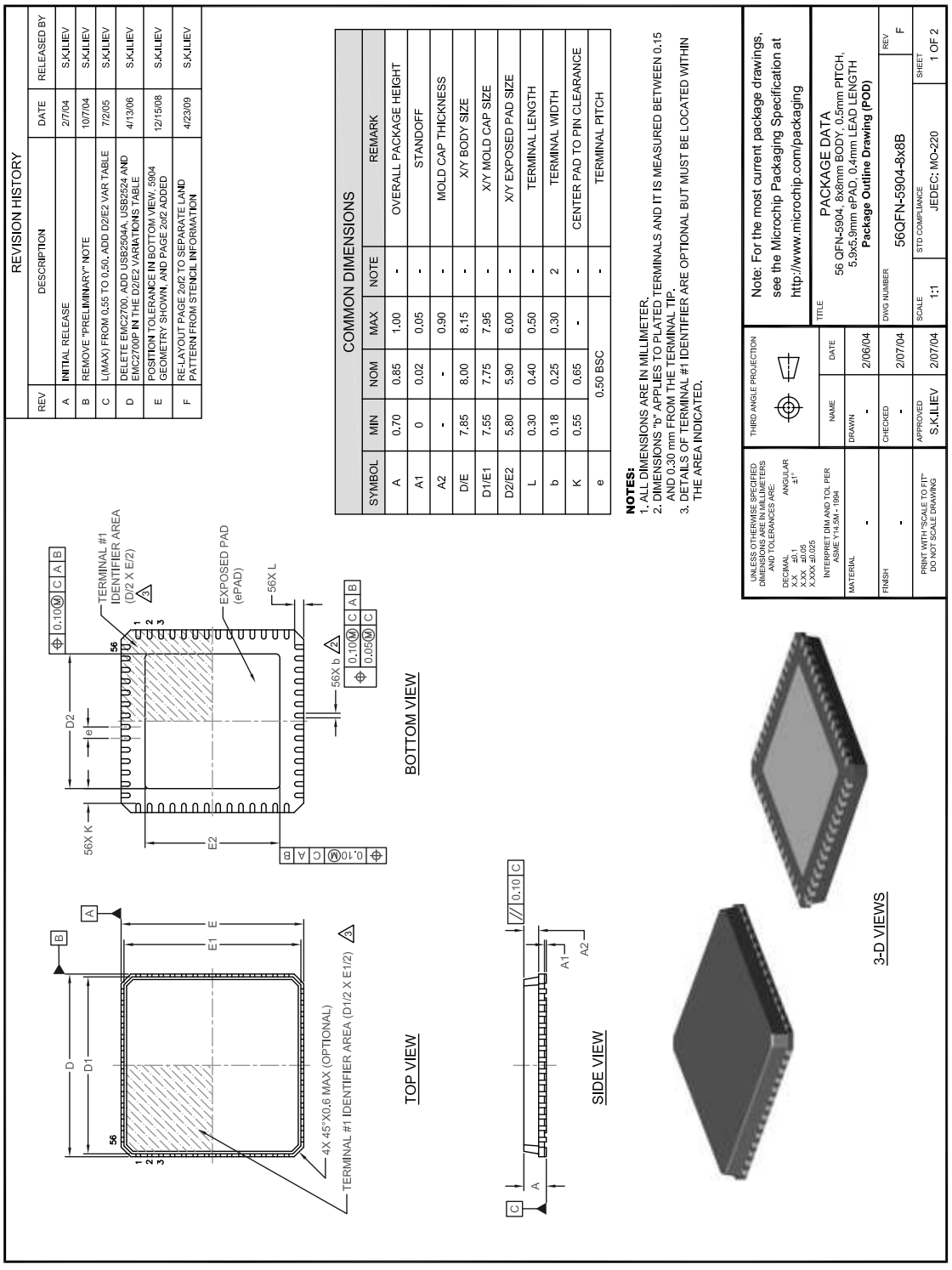
Note 7-26 70ºC for commercial version, +85ºC for industrial version.

Note 7-27 This number includes the pad, the bond wire and the lead frame. PCB capacitance is not included in this value. The XI pin, XO pin and PCB capacitance values are required to accurately calculate the value of the two external load capacitors. The total load capacitance must be equivalent to what the crystal expects to see in the circuit so that the crystal oscillator will operate at 25.000 MHz.

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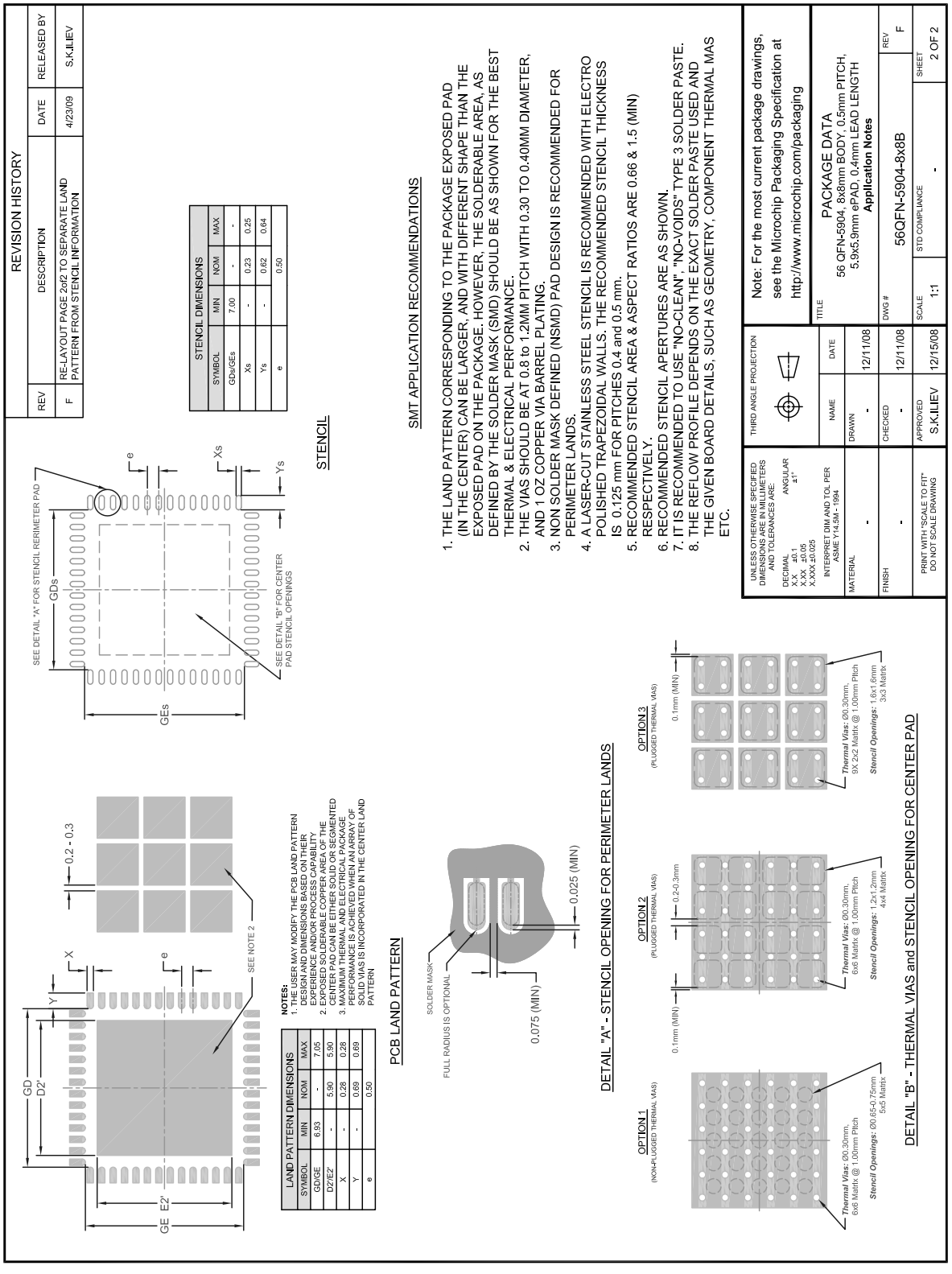
8.0 PACKAGE OUTLINE

FIGURE 8-1: LAN7500/LAN7500I 56-QFN PACKAGE



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FIGURE 8-2: LAN7500/LAN7500I 56-QFN RECOMMENDED PCB LAND PATTERN



APPENDIX A: REVISION HISTORY

TABLE 8-1: REVISION HISTORY

Revision Level and Date	Section/Figure/Entry	Correction
DS00001374B (07-22-16)	All	Document converted to Microchip look and feel.
	Section 7.2, "Operating Conditions**," on page 34	XTAL1 Absolute Maximum input voltage level reduced to 3.6V.
	Table 7-11, “I/O Buffer Characteristics,” on page 40	XTAL1 High-Level Input voltage maximum reduced to 3.6V. XTAL1 Minimum Input High level reduced to 0.9V
	Section 7.6, "Clock Circuit," on page 47	Updated to add Section 7.6.2, "100uW 25 MHz Crystal Specification," on page 48.
	Section 7.6.1, "300uW 25 MHz Crystal Specification," on page 47	Updated to add Figure 7-7.
DS00001734A replaces the previous SMSC version, rev. 1.0		
Rev. 1.0 (11-01-10)	All	Initial Release.

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PART NO.	[X]	-	XXX	-	[X](1)
Device	Temperature Range		Package		Tape and Reel Option

Device:	LAN7500
Temperature Range:	Blank = 0°C to +70°C (Extended Commercial) i = -40°C to +85°C (Industrial)
Package:	ABZJ = 56-pin QFN RoHS compliant package
Tape and Reel Option:	Blank = Standard packaging (tray)

Examples:

a) LAN7500i-ABZJ
Industrial temperature,
56-pin QFN
Tray

b) LAN7500-ABZJ
Extended commercial temperature,
56-pin QFN
Tray

Note: This product meets the halogen maximum concentration values per IEC61249-2-21

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ISBN: 978-1-5224-0797-3

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